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MORE THAN 40 YEARS OF MADE-IN-ITALY INNOVATION

Founded in 1979, ASEM has actively operated through the entire information and digital technology evolution, continuously anticipating market changes and maturing an important wealth of expertise.

ASEM is an IPC market leader in Italy and has been a key player in the Industry 4.0 evolution for some time, with the integration of the UBIQUITY remote assistance software platform on all systems and then with the definition of the new HMI paradigm through the UNIQO Full OPC UA visualisation platform.

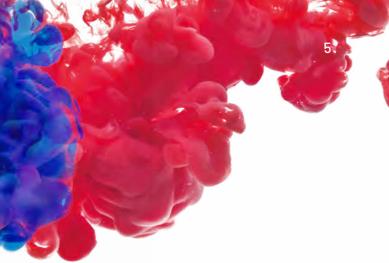
A CONTRACTOR OF THE OWNER

240 + employees

30% dedicated to R&D



MILESTONES 1979 / 1982 Specialisation in Electronic Engineering 1983 / 1992 Protagonist in the IT sector @ASEM• 1993 / 2005 **LEADERSHIP IN THE** In the mid-'90s, ASEM is the first company in Italy **INDUSTRIAL PC MARKET** that designs and produces Industrial PCs specifically addressed to the Industrial Automation market. In 2020, ASEM joined the Rockwell Automation Group, the world's largest company dedicated to 2006 / 2008 MANUFACTURER OF Thanks to agreements with leading companies, industrial automation and manufacturing infor-**AUTOMATION SYSTEMS** ASEM offers the market the Premium HMI and mation management, headquartered in Milwaukee CODESYS (softPLC) software platforms. (USA) and with a major presence in the EMEA, Asia PREMIUMHMI Pacific and Latin America regions. Expansion in Europe 2010 2011/2012 SOFTWARE AND REMOTE The innovative UBIQUITY remote assistance **ASSISTANCE ERA** software platform for remote access to supervision systems and automation devices is released. 2016 OPC UA in the PremiumHMI5 platform 2019 **THE 4.0 REVOLUTION OF HMI** The innovative UNIQO software platform, based **IS REALITY** on a "Full OPC UA" multi-platform framework, was released. ASEM A ROCKWELL AUTOMATION COMPANY 2020 Rockwell Automation





This allowed ASEM to grow in a global context and become the centre of excellence of the group for hardware, visualisation and integrated systems with application software.



LOCATIONS



• Software R&D

Sales

ASEM Artegna HEADQUARTERS

- Hardware, Software & Systems R&D
- Quality

- Strategic Sourcing Sales & Marketing Administration, Finance & Controlling
- Human Resources
- Boards manufacturing & Assembling
- Systems assembling
- Testing
- Maintenance & Facility Management
 Logistic & Warehouse
- Hardware & Systems support

ASEM Bologna • Software R&D

Sales

ASEM Giussano

- Software & Systems R&D
- Hardware & Systems support

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• Sales



@ASEM•



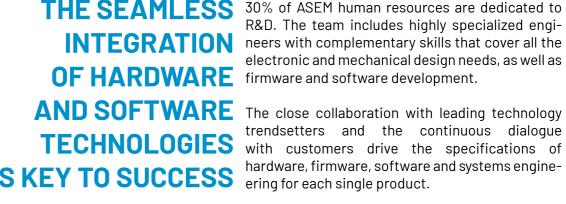


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MAXIMUM SYSTEM CONFIGURABILITY AND FLEXIBILITY

ASEM has a complete range of industrial PCs, human-machine interface (HMI) solutions, remote assistance and industrial IoT gateways. With its know-how, technological expertise, flexibility and ability to customise its product portfolio, ASEM leads customers on the way towards digital transformation by providing innovative and scalable solutions to improve all stages of production processes related to the evolution in progress

CLOUD



MECHANICAL DESIGN

- 3D modelling and simulation of mechanical assembly and coupling
- Analysis and thermal simulations for dissipation dimensioning
- Integration of mechanical and electronic CAD for more efficient and precise design



OPERATING SYSTEMS & FIRMWARE DEVELOPMENT

- Development, testing and customisation of operating systems for IPCs
- Development, testing and customisation of operating systems for ARM platforms
- Development and testing of drivers for x86 platforms
- Development and testing of BIOS for x86 platforms
- Configuration and testing of systems for real-time applications

THE SEAMLESS 30% of ASEM human resources are dedicated to R&D. The team includes highly specialized engi-**INTEGRATION** neers with complementary skills that cover all the electronic and mechanical design needs, as well as

trendsetters and the continuous dialogue **TECHNOLOGIES** trendsetters and the continuous dialogue with customers drive the specifications of **IS KEY TO SUCCESS** hardware, firmware, software and systems engine-ering for each single product.

ELECTRONIC DESIGN

- Designing motherboards based on Intel[®] x86 and ARM NXP platforms
- Creation of PCB masters
- Verification of signal integrity through CAD simulation
- In-house laboratory for EMC compatibility testing



SOFTWARE DEVELOPMENT WITH AGILE METHODOLOGY

- DevOps
- Extreme Programming (XP)
- Lean Software Development

HIGH-QUALITY PRODUCTION

SS

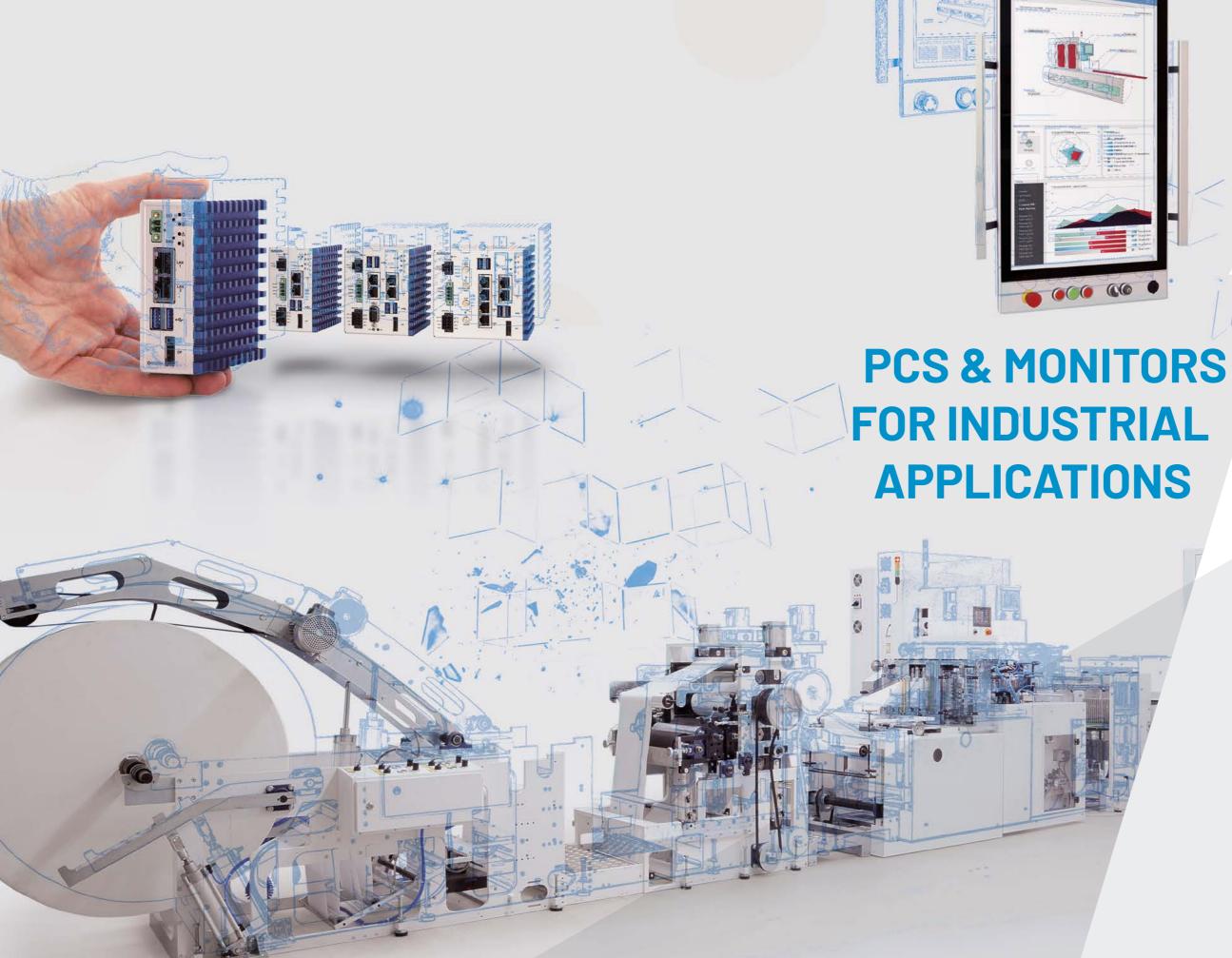
ASEM manufactures and assembles its electronic boards, products and systems in its own industrial facilities in Artegna, covering a total area of over 8,500 square metres.

BOARD ASSEMBLY

- Acceptance and stock control (Kardex)
- B.O.M. (Component Selection & Management)
- Pick & Place machine programming
- 3 complete SMT lines
- Remelting furnaces (Ersa)
- Screen printers with integrated Post Print AOI (Ersa)
- Selective soldering machine for Through Hole technology
- Visual board inspection
- X-ray inspection
- Functional Testing
- Power supply voltage test of boards with bed of nails
- Functional test of boards for eight hours (3 cycles)
- Active burn-in test (0°- 50° / 24H cycles)

SYSTEM ASSEMBLY

- B.O.M.
- System assembly (mechanical and electronic)
- Imaging of the operating system on mass memories
- Complete functional test of final system
- Run-in test (8H)
- Final Check & Packaging



FLEXIBILITY AND INNOVATION

ASEM offers a complete range of reliable, robust, highly configurable and expandable te assistance and can optionally integrate UNIQO industrial PCs and monitors, with a panel, arm, wall or DIN-rail mounting arrangement to meet diverse market requirements.

All IPCs integrate UBIQUITY software for remosoftware to set up modern HMIs, IIoT gateways and Industry 4.0 applications or CODESYS software that transforms ASEM systems into powerful controllers.



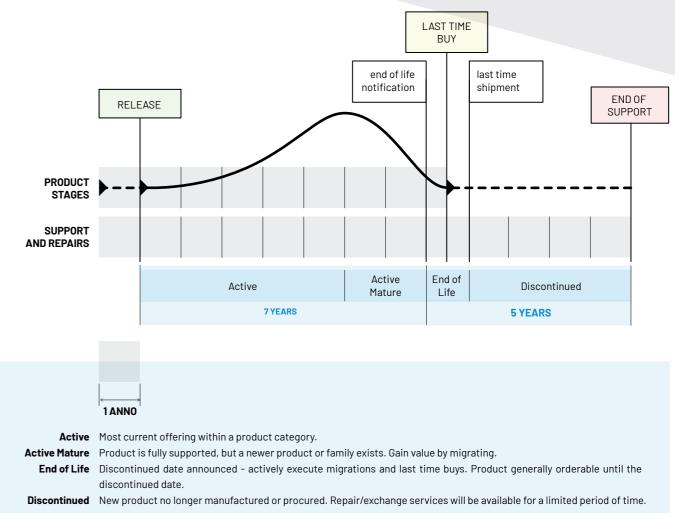


SCALABLE PERFORMANCE, EXPANDABILITY AND CONFIGURATION

The market demands high-performance systems, more computational power, better graphics, integrated IIoT functionality and reduced power consumption. The ASEM IPCs use Intel® processors, ranging from low-power Atoms for entrylevel applications, up to the highest performance eleventhgeneration Intel[®] CoreTM processors for higher performance, next-generation graphics and integrated connectivity. The motherboards of the systems allow various levels of expandability in terms of communication interfaces and expansion slots and minimise internal wiring and connections to make the systems more reliable and resistant even to the potential vibrations typical of industrial environments.

CONNECTIVITY AND COMMUNICATION

To respond to multiple industrial applications, the need for communication between industrial networks and computer networks, and the most recent needs arising from the Industry 4.0 revolution, with increasingly connected and automated smart factories requiring advanced connections between MES systems, ERPs and production machines, ASEM offers systems equipped with wireless connectivity using combined Wi-Fi 5 and Bluetooth modules and 4G Global modems in addition to traditional connectivity through wired networks. Furthermore, TSN technology is integrated into the systems to ensure ultrareliable low-latency machine-to-machine communications at Gigabit speeds, significantly contributing to improving the performance and efficiency of real-time processes. Optionally, UNIQO, the Full OPC UA cross-platform software platform, can be integrated into the systems for the developing HMI applications, IIoT and Industry 4.0 solutions capable of communicating with any automation device.



The superior design and production processes combined with close collaboration with technological trendsetters allow ASEM to guarantee a life cycle of at least 7 years for systems and repairability, with the availability of spare parts, for at least a further 5 years. End of Life, Last Time Buy and Last Time Shipment procedures are in place 6 months before the end of each product's life cycle.

DESIGN, ERGONOMICS AND RELIABILITY



The complete control of all stages of the production process, and over 40 years of experience in mechanical design and industrialisation allow ASEM to produce IPCs and industrial monitors with Italian-style design, with attention to every detail, and high reliability and durability. Chassis are generally made of galvanised steel, aluminium or stainless steel and are the result of industrialisation based on perfect integration between electronic boards and mechanical components and accurate thermodynamic and fluid-dynamic analyses.

SYSTEM TRACEABILITY

The ASEM systems integrate "ASEM System Identity", a non-volatile memory that contains system identification data in addition to customer data useful for system traceability.

OPERATING SYSTEMS

Operating systems are continuously updated and ASEM ensures full compatibility of x86 systems with Windows operating systems and Linux distributions. The ASEM Team also supports the implementation of customer-made images and develops customised images to be applied to its systems. The complete control of all stages of the production process, and over 40 years of experience in mechanical design and industrialisation allow ASEM to produce IPCs and industrial monitors with Italian-style design, with attention to every detail, and high reliability and durability. Chassis are generally made of galvanised steel, aluminium or stainless steel and are the result of industrialisation based on perfect integration between electronic boards and mechanical components and accurate thermodynamic and fluid-dynamic analyses.





The ASEM IPC panels and monitors are designed to meet all aesthetic, ergonomic and robustness requirements and guarantee a degree of protection up to IP69K, making them the ideal solution for any industrial application, even the most demanding. LCDs are available with LED-backlit displays in 4:3, 5:4 and wide formats, from 7" to 24", with resolutions including Full HD.

GASED

The unique cut-out allows perfect interchangeability between IPC QT/HT panel families and MQ/ MH monitors. The QT systems differ from the HT systems in their minimised frame, with a more modern and sophisticated design.

DISPLAY	.	"HT" C	ut-Out	"QT" C	ut-Out
SIZE	Ratio	L	н	L	н
7"W A	15:10	207	159	-	-
7"W B	15:10	197	141	196	140
8.4"	4:3	230	190	-	-
10.1"W	16:10	277	196	256	174
10.4"	4:3	280	225	-	-
12.1"	4:3	315	250	-	-
12.1"W	16:10	313	218	301	203
15"	4:3	370	295	-	-
15.6"W	16:9	410	255	388	238
17"	5:4	435	335	-	-
18,5"W	16:9	480	300	453	275
19"	5:4	470	368	-	-
21.5"W	16:9	559	347	520	312
24"W	16:9	620	382	577	344







ALUMINUM FRONT PANEL (ALU) AND RESISTIVE TOUCHSCREEN

The front panel is made of anodised aluminium with IP65 protection against dust and water jets. This panel integrates a 5-wire resistive touchscreen offering high shock resistance and the possibility of pressing on the screen not only with the fingers but also with other objects, such as a stylus, achieving a very high degree of precision. Monitors with resistive touchscreens also work in extended temperature ranges, even in very humid environments. The HT systems have a USB interface on the front.

TRUE FLAT ALUMINIUM FRONT PANELS (TF) AND RESISTIVE TOUCHSCREEN

True Flat technology guarantees a perfectly flat surface, without recesses, completely insulated from external agents and allows for easier cleaning of the panel. This technology also allows the perfect integration of the touchscreen and the frame, making the front panel more pleasing to the touch and in appearance. ASEM manufactures these panels with a special production process inside a cleanroom to avoid environmental contamination such as dust or microbes in the air. The panels are completely dust-tight and protected against water jets with an IP65 rating and incorporate the 5-wire resistive touchscreen.



TRUE FLAT ALUMINIUM FRONT PANELS (TFM) WITH GLASS PROJECTED CAPACITIVE MULTITOUCH SCREEN.

Wide-format front panel with a sturdy aluminium frame, tempered glass surface with True Flat technology for maximum resistance to environmental conditions and easy cleaning. This front panel integrates the rear-projected

capacitive touchscreen.

The glass surface layer gives the screen greater image brilliance and sharpness, greater scratch resistance and less wear and tear. The user experience is more pleasant than with resistive touchscreens due to the high touch sensitivity. The capacitive touchscreen allows interaction with various elements on the screen through gestures typical of the mobile world, such as zooming, swiping and rotating (even with gloves) with high touch sensitivity and a high level of precision.

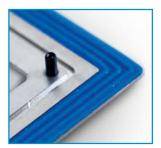
The capacitive touchscreen supports up to 10 simultaneous touches.

In ASEM systems, the capacitive multitouch touchscreen is integrated into the TFM monitors.



STAINLESS STEEL FRONT PANELS (TFK)AND RESISTIVE TOUCHSCREEN

Front panel in stainless steel (AISI304L) with IP69K degree of protection, particularly suitable for the pharmaceutical and Food & Beverage markets, where maximum protection against high-pressure washing and dust penetration is required. TheTFKfrontpanelfeaturesaresistivetouchscreen.



It also features hygienic silicone seals and the durable front film is specially designed to withstand numerous washing cycles with high-pressure water

FOR REMOTE ASSISTANCE, VISUALISATION, IIOT, **INDUSTRY 4.0 AND CONTROL**

APPLICATION SOFTWARE

PREMIUM

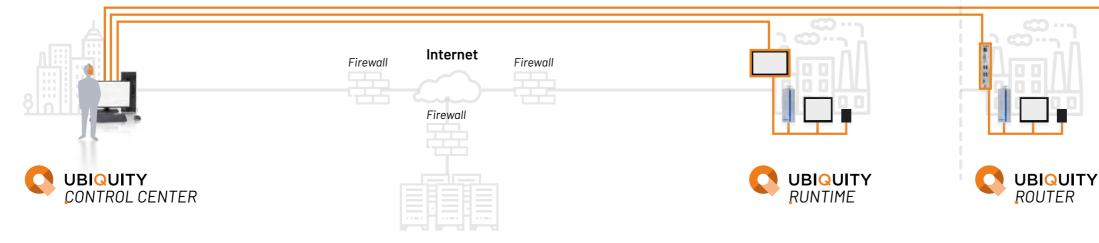
CODESYS

23



INTEGRATED REMOTE ASSISTANCE IN ALL IPCS

Comprehensive, secure and certified technology for remote assistance using interactive services and optimised VPN connection for access to the automation subnetwork.



UBIQUITY Server Infrastructure



Available both as a software solution for WinCE, Win32/64 and Linux systems and as an all-in-one router solution, also with a 4G Global Wi-Fi Modem and 4-port Ethernet switch. Installation does not require IT skills to configure the networks and various firewalls, the use of which is facilitated by a user-friendly interface that allows access to remote systems (PLCs, inverters, drives, etc.) with a simple click using a VPN optimised for industrial communications.

The solution allows the transparent management of remote systems as if they were connected to the customer's corporate network, bypassing the network administrator's intervention on any NATs, proxies, firewalls, public IPs or reserved ports, with the advantage of having all the company's expertise available to solve any arising problems, eliminating distances and the need for on-site travel and drastically slashing after-sales assistance costs. UBIQUITY is also particularly useful in the installation and commissioning phases of machinery to make changes and updates to application software and for the remote debugging of PLCs or other automation devices.



In recent years, ASEM has expanded the offerings of the UBIQUITY remote service platform by offering a set of closely related innovative services, called UBIQUITY X. Cloud-based and seamlessly integrated into the infrastructure, they help automated machine builders and industrial system integrators meet the emerging demands of manufacturing companies committed to transforming traditional factories into digital Smart Factories. The main service of UBIQUITY X is the possibility of assisting with the aid of augmented reality through the new "UBIQUITY AR" (Augmented Reality) application, available for iOS and Android devices, which amplifies the experience of both the operators of the automatic machines and the service technicians during remote assistance.

UBIQUITY has long since been certified as compliant with IEC 62443, which covers the IT security of industrial communications using the Internet as a transport medium, and also includes a two-factor authentication mode using standard apps for iOS and Android



VISUALISATION, IIOT AND INDUSTRY 4.0

UNIQO, the universal software platform for all industrial applications with a completely modular and extremely flexible architecture, springs from the analysis of the needs of automated machine manufacturers and industrial system integrators to provide them with innovative, high-performance, yet flexible and easy-to-use programming tools. UNIQO can be used to make:

- Ergonomic and intuitive HMIs with an unprecedented user experience
- IIoT gateways, Edge Computing applications and general Industry 4.0 solutions

UNIQO is developed with cross-platform technologies compatible with ARM and x86 architectures, Windows and Linux operating systems and includes support for HTML5 browsers. UNIQO fully supports the specification of the OPC UA standard and can be defined as a "FULL OPC UA" software platform for making dynamic client/server architectures, in which systems alternate in the role of producers and consumers of the most varied types of information, allowing any application realised with UNIQO to be able to communicate with any automation device.



With UNIQO, the OPC UA can be used for

- data acquisition from the field
- machine-to-machine (M2M)
- information exchange interfacing to MES, ERP business management systems
- interfacing to Cloud infrastructures

A system with UNIQO can share data and also application functions by allowing an external OPC UA client to actively and dynamically interact with all project functions, such as user configuration, recipes or even the graphic resources of screens, for instance. UNIQO reduces application development time and ensures fast responses to customers' customisation requests at any point in the machinery life cycle.

PREMIUM

SCALABLE, OPEN AND FLEXIBLE OPERATOR INTERFACES



With the Premium HMI software platform, ASEM has been marketing visualisation systems for some time now. The solutions are highly appreciated for the quantity and quality of the functions available and for the transversal nature of the platform allowing any one project to be used indifferently on HMI solutions based on ARM or x86 hardware platforms and with Runtime for WinCE or Win 32/64 operating systems without any need to modify or change settings in the "Premium HMI Studio" development tool. Several releases of this tried and tested platform have been released over the years. Since the 5.1 Premium version, HMI supports OPC UA Server functions for both Windows 32/64 and Windows CE systems. Premium HMI 5.1 is the optimal solution for the realisation of interoperable applications compatible with Industry 4.0 standards. A Premium HMI project can be conveniently configured to acquire field data through PLC communication protocols and the OPC UA client and then share it, through the OPC UA Server, with other systems or machines, to achieve optimal integration in the most heterogeneous scenarios. Premium HMI 5.1 supports the use of Active Directory services to authenticate HMI project users through direct interfacing with Domain Controllers, by simplifying the implementation of CFR 21 Part 11 compliant applications.

With the user-friendly object-oriented design, project debugging tools and the possibility of using a single development environment for any type of application (from the simplest on operator panels to the most complex on IPC panels or the most innovative on intelligent mobile devices), the Premium HMI it is easy to achieve significant time savings in learning, personnel training, maintenance, support and end-user service.

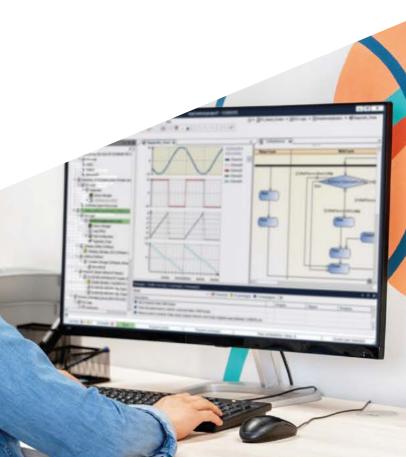
Premium HMI Mobile is the ASEM app that offers the possibility to view and interact with Premium HMI projects running on the operator terminal of the industrial machine also from iOS and Android devices connected through Wi-Fi local area network to the factory network, offering mobile and multitouch support to project management.



FLEXIBLE CONTROL OF PLC AND MOTION LOGIC IN A SINGLE DEVELOPMENT TOOL

CODESYS is a global standard in industrial automation and the world's number one SoftPLC platform, independent of multinational PLC manufacturers. Integrated into ASEM IPCs, it transforms systems into powerful IEC 61131-3 controllers with a highly efficient implementation of the 3.5 version that guarantees deterministic execution of PLC control logic with Win 32/64 and Linux operating systems and full portability of projects between different operating systems and hardware platforms with no need for intervening on the project code. The CODESYS platform, like all traditional PLCs, provides a development environment (CODESYS Engineering) for making projects, which are then executed by the runtime, and the availability of the most popular industrial fieldbuses in master mode (such as CANopen, Profibus, Profinet, Ethernet/IP, Ether-CAT, Modbus RTU and Modbus TCP) for communication with field peripherals.

To ensure data flow traceability and information historisation, the ASEM IPCs optionally include a UPS power supply with integrated electronics and an external battery and 512Kb of MRAM (Magnetoresistive RAM) for storing retentive variables.



PORTFOLIO OVERVIEW







PANEL IPCS

P. 34-54

IPC Panels are low-power, high-performance systems, available with a wide choice of TFT LCDs from 7" to 24" and various types of front panels. The wide range of IPCs can meet all performance, configurability and expandability requirements in the industrial environment.

BOX IPCS				P. 58	3-78
QT3400/3600 & HT3400/3600	p.42	QT3500 & HT3500	p.46	QT5400/5600 & HT5400/5600	p.50
QT2150 & HT2150	p.34	QT2200 & HT2200	p.36	QT2250 & HT2250	p.40

IPC boxes are systems for wall-mounted and book-mounted installations, which meet all performance and installation space requirements. They offer extensive expandability with a large number of accessories and interface expansion cards.

PB2150 & BM2150	p.58	PB2200 & BM2200	p.60	PB2250 & BM2250 p.62
BM3300	p.64	PB3400/3600 & BM3400/3600	p.66	PB3500 & BM3500 p.70
PB5400/5600	p.74			

ULTRA-COMPACT IPCS

P. 82-86

Ultra-compact IPCs are extremely ergonomic, robust systems that are ideal for applications in small spaces where high processing capacity is required.

The product range provides a wide configurability to meet the needs required in many IIoT scenarios.

BM1XY FAMILY p.82 **PRODUCT RATINGS**

All products were evaluated according to three parameters:

(P) PERFORMANCE EXPANDABILITY



The arm mounting IPCs are fanless, compact, elegant systems that offer excellent performance and can be used in various industrial applications due to their high configurability. They are available with a customisable control area and various accessories that improve ergonomics, providing a wide range of customisation possibilities.

² = =

CONFIGURABILITY

VK3500

versions.

PR4XXX

Industrial monitors have the same robust, reliable and aesthetic characteristics as IPC panels. They are available with different installation modes, with the possibility for some systems to integrate a configurable control area and various accessories. All monitors integrate RVL technology for remote DVI-D and USB 2.0 signals up to 100m.

M0200 & MH200



ARM/VESA MOUNTING IPCS

p.90

RACK MOUNTING IPCS

The rack mounting IPC 19" 4U devices offer high computing capacity and high reliability using heavy-duty motherboards for 24/7 industrial applications. They are available in long and short

p.94

INDUSTRIAL MONITORS

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PANEL IPCS

EXTENSIVE CONFIGURABILITY AND EXPANDABILITY

01016565659 56513174

8231151 1548412215 1843748

3465186451

81982

HHE

HIGH PERFORMANCES LOW CONSUMPTION

33

QT2150 & HT2150



 TFT LCDs in 8.4", 10.4", 12.1", 15" in 4:3 aspect ratio and 7", 10.1", 12.1", 15.6" in Wide aspect ratio FANLESS

×

- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Intel[®] Celeron[®] processors of Bay Trail SoC generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth and SO version with the possibility to install additional interfaces

TECHNICAL DATA

		QT2150-ALU	QT2150-TFM	HT2150-ALU	HT2150-TF	HT2150-TFM		
LED BACKLIGHT TFT LCD		10.1″ W - 12.1″ W -	000×480 1280×800 1280×800 1366×768	7" W - 8 8.4" - 8 10.1" W - 10.4" - 8 12.1" - 8 12.1" - 10 12.1" W - 15" - 10 15.6" W -	7" W - 800x480 10.1" W - 1280x800 12.1" W - 1280x800 15.6" W - 1366x768			
CUT-OUT		Ç						
FRONT USB			-	1x USB 2.0 (Typ	e-A), protected	-		
TOUCHSCREEN		Resistive 5 wires P-CAP Multitouch Resistive 5 wires				P-CAP Multitouch		
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum		e Flat ninum		
	ASEM Logo		-	Adhesive label	Silk screen printed			
PROTECTION	IP rating			IP65 - frontal				
GRADE	NEMA rating	UL Type 1, 4>	(indoor only)	UL T	/pe 1, 4x (indoor only)	and 12		
CASE	Installation			Panel mounting				
	Material		Zi	nc-coated skin pass st	eel			
PROCESSOR (soldered of	on-board)	Intel® Celer	on® J1900 2.00Ghz (2.3	30GHz Burst) • 4 cores	/ 4 threads • 2MB L2 c	ache•22nm		
CHIPSET			Intel® Bay Trai	I • Included into proces	ssor chip (SoC)			
VIDEO CONTROLLER		Intel® HD Graphics for Intel Atom® processor Z3700 series • 688MHz/854MHZ						
SYSTEM MEMORY RAM		1GB or 2GB or 4GB or 8GB SODIMM DDR3L module						
MASS STORAGE	CFast	1x I	bootable CFast SATA II	slot onboard with exte	ernal access (up to 240)GB)		
	SSD mSATA	1 x on	board connector for d	rect insertion of mSA	FA SSD SATA II (up to 9	60GB)		
	LAN	2x Gigabit Ethernet (RJ45)						
INTERFACES	USB	1x USB 3.0 (Type-A) • 1x USB 2.0 (Type-A)						
	VIDEO		-					
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version		1x RS232/422/48		USB 2.0 (Type-A) 2.0 (Type-A) Hz/5GHz • Bluetooth 4			
POWER SUPPLY INPUT			24	VDC (18÷32VDC) isolat	ed			
POWER SUPPLY	UPS		UPS with ex	ternal battery pack (Pt (separate mounting)	• 12V/2,5Ah)			
(optional)	ATX only S0 version	Kit for ATX m	node power supply (pus	h button, internal cabl	e and connector for re	emote control)		
BATTERY			1×	CR2032 Internal acce	SS			
0.S. CERTIFIED		Microsoft Windows 7 Pro/Ultimate 32/64bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit Microsoft Windows 10 IoT Enterprise 2016/2019 64 bit						
OPERATING TEMPERATU	JRE	0°C ÷ 50°C						
STORAGE TEMPERATUR	E	-5°C ÷ 60°C						
OPERATING/STORAGE	RELATIVE HUMIDITY		20%	÷ 90% RH (non-conder	nsing)			
APPROVALS		20% ÷ 90% RH (non-condensing) CE cULus Listed						

QT2200 & HT2200



- TFT LCDs in 10.4", 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 10.1", 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU), aluminum True Flat (TF) and stainless steel True Flat (TFX) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen(TFM)
- Intel[®] Celeron[®] processors of Bay Trail SoC generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors µUPS, with 512kB MRAM for retentive data management (optional)
- Available in SL version with reduced depth, SO version with the possibility to install additional interfaces and S1 version with PCI or PCIe expansion slot

GALLERY

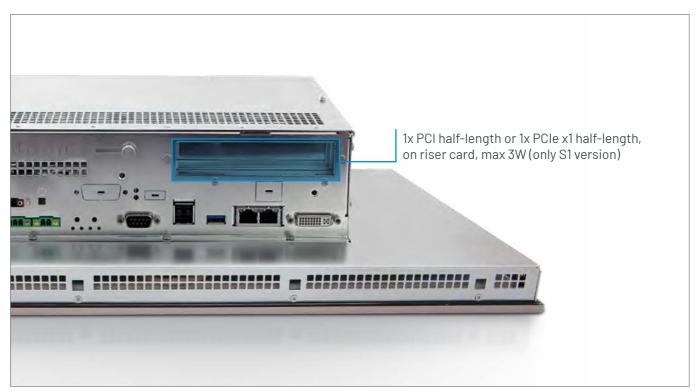


QT2200 & HT2200 - (SL Version)



QT2200 & HT2200 - (S1 Version)

DETAIL - EXPANSION SLOTS









QT2200 & HT2200 - (SO Version)

QT2200 & HT2200

TECHNICAL DATA

		QT2200 - ALU	QT2200 - TFM	HT2200 - ALU	HT2200 - TF	HT2200 - TFX	HT2200 - TFM	
LED BACKLIGHT TF	T LCD	12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080		10.1" W - 1280x800 (only SL) 10.4" - 800x600 12.1" - 800x600 12.1" - 1024x768 12.1" W - 1280x800 15.0" - 1024x768 15.6" W - 1366x768 15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1320x1080 19" - 1280x1024 21.5" W - 1920x1080 24"W - 1920x1080		12.1″ - 800x600 12.1″ - 1024x768 15.0″ - 1024x768 17″ - 1280x1024 19″ - 1280x1024	10.1" W - 1280x800 (only SL) 12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080	
CUT-OUT			QТ			HT		
FRONT USB			-	1x USB 2.0 (Type	e-A), protected		-	
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wire	S	P-CAP Multitouch	
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Flat Aluminum	True Flat Stailness Steel	True Flat Aluminum	
	ASEM Logo		-	Adhesive label	Silk-scr	een printed	-	
PROTECTION	IP rating		IP65 -	frontal IP66K - frontal			IP65 - frontal	
GRADE	NEMA rating	UL Type 1, 4	4x (indoor only)	UL Type 1, 4x (indoor only) and 12				
CASE	Installation			Par	el mounting			
	Material			Zinc-coat	ted skin pass ste	el		
PROCESSOR (solde	ered on-board)	Intel® Ce	eleron® J1900 2.00	GHz (2.42GHz Bur	st)•64bit•4 cor	es / 4 threads • 2M	B L2 cache • 22nm	
CHIPSET			Inte	el® Bay Trail • Inclu	ded into proces	sor chip (SoC)		
VIDEO CONTROLLE	R		Intel® HD Graph	ics for Intel Atom®	processor Z370	0 series • 688MHz/	854MHz	
WATCHDOG				Program	mable time perio	bd		
TPM				Discrete TPM	2.0 module (op	tional)		
SYSTEM MEMORY R	AM		1GB	or 2GB or 4GB or 8	GB (1x SODIMM	DDR3L module)		
MASS STORAGE	CFast		1x bootable CF	ast SATA II slot on	board with exte	rnal access (up to 2	40GB)	
(SSD mSATA and SSD/HDD alter-	SSD mSATA		1x onboard conn	ector for direct in	sertion of SSD m	nSATA SATA II (up to	960GB)	
native to each other)	SSD/HDD only SO/S1 versions		1x onboard conn	ectors for SSDs/H	DDs 2,5" SATA II	with internal instal	lation kit	
	LAN			2x Gigab	it Ethernet (RJ4	5)		
INTERFACES	USB			2x USB 2.0 (Type	e-A)•1x USB 3.0	(Туре-А)		
	SERIAL			1x R	S232 (DB9M)			
	VIDEO		1x DVI-I	(Resolution up to	1920x1080 • VGA	adapter included)		
ADD-ON INTERFACES (optional)	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)						
not available for SL version	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2)1 and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)1						
EXPANSION SLOTS	only S1 version		1x PCI half	-length or 1x PCIe	x1 half-length, o	n riser card, max 3	W	
POWER SUPPLY IN	PUT			24VDC(18	8÷32VDC) isolate	ed		
POWER SUPPLY (optional)	UPS Backside mounting not available for SL version		U	PS with external b (backside or	oattery pack (Pb r separate moun			

TECHNICAL DATA

		QT2200 - ALU	QT2200 - TFM	HT2200 - ALU	HT2200 - TF	HT2200 - TFX	HT2200 - TFM			
POWER SUPPLY	UPS + 512kB MRAM Backside mounting not available for SL version	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (backside or separate mounting)					1			
(optional)	µUPS + 512kB MRAM			Supercapacito	ors µUPS + 512kB	MRAM				
	ATX only SO/S1 versions	Kit for	Kit for ATX mode power supply (push button, internal cable and connector for remote control)							
BATTERY		1x CR2032 Internal access								
0.S. CERTIFIED			Micros	Microsoft Windov soft Windows Emb osoft Windows 10	bedded Standard	7E/7P 32/64 bit				
OPERATING TEMPE	RATURE		0°C	÷ 45°C (24x7 HDD)°C ÷ 50°C) or Intel® Core™ °C (Standard HDI					
STORAGE TEMPER	ATURE			-1	0°C ÷ 60°C					
OPERATING/STOR	AGE RELATIVE HUMIDITY			20% ÷ 90%	RH (non-conden	sing)				
APPROVALS		CE UL 508 CE UL 508 ATEX zone 2/22 CE UL 508								

1. Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.

QT2250 & HT2250

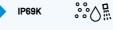


- TFT LCDs in 10.4", 12.1", 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 7", 10.1", 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel (AISI 304L) True Flat (TFK) front panel with resistive touchscreen
- Intel Atom[®] x5 and x7 processors of Apollo Lake SoC generation
- RAM up to 8GB
- Available in SL version with reduced depth and SO version with the possibility to install additional interfaces

TECHNICAL DATA

		QT2250-ALU	QT2250-TFM	QT2250-TFK	HT2250-ALU	HT2250-TF	
LED BACKLIGHT TF	T LCD		7" W - 800x480 10.1" W - 1280x800 12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18,5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24" W - 1920x1080		10.4" - 800x600 12.1" - 800x600 12.1" - 1024x768 15" - 1024x768 17" - 1280x1024 19" - 1280x1024		
CUT-OUT			QΤ		ŀ	IT	
FRONT USB			-		1x USB 2.0 (Typ	e-A), protected	
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires		
FRONT PANEL	Material	Aluminum	True Flat Aluminum	True Flat Stainless Steel	Aluminum	True Flat Aluminum	
	ASEM Logo		-		Adhesive label	Silk screen printe	
PROTECTION	IP rating	IP65 -	frontal	IP69K - frontal	IP65 -	frontal	
GRADE	NEMA rating	U	L Type 1, 4x (indoor onl	y)	UL Type 1, 4x (in	door only) and 12	
CASE	Installation			Panel mounting			
CASE	Material		Zi	nc-coated skin pass st	eel		
PROCESSOR (solde	ered on-board)		Intel Atom® x5-E3930 1.30Ghz (1.80Ghz Burst) • 64bit • 2 cores / 2 threads • 2MB L2 cache • 14nm Intel Atom® x7-E3950 1.60Ghz (2.00Ghz Burst) • 64bit • 4 cores / 4 threads • 2MB L2 cache • 14nm				
CHIPSET			Intel® Apollo La	ke • Included into proc	essor chip (SoC)		
VIDEO CONTROLLE	R		I® HD Graphics 500 inte I® HD Graphics 505 inte				
ТРМ			Intel® PTT (TPM integ	grated) • Discrete TPM	2.0 module (optional)		
SYSTEM MEMORY	with x5-E3930	4GB LP-DDR4 module					
RAM	with x7-E3950		4G	B or 8GB LP-DDR4 mo	dule		
MASS STORAGE	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)					
	M.2 SSD	1x onboard connector for direct insertion of M.2 2242 SATA III SSD (up to 480GB)					
	LAN		2)	Gigabit Ethernet (RJ4	45)		
INTERFACES	USB			3x USB 3.0 (Type-A)			
	VIDEO			1x DisplayPort++ V1.2			
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM		1x RS232/422/48	2/485 (DB15M) + 1x USE 5 (DB15M) isolated + 1x 2x USB 2.0 (Type-A) hernet (RJ45) + 1x USE	USB 2.0 (Type-A)		
POWER SUPPLY IN	PUT		24	VDC (18÷32VDC) isolat	ed		
POWER SUPPLY (optional)	ATX only S0 version and BM	Kit for ATX m	node power supply (pus	h button, internal cabl	e and connector for re	emote control)	
BATTERY			1×	CR2032 Internal acce	SS		
0.S. CERTIFIED			Microsoft W	ndows 10 IoT Enterpris	se 2019 64 bit		
OPERATING TEMPE	RATURE			0°C ÷ 50°C			
STORAGE TEMPER	ATURE	-5°C ÷ 60°C					
OPERATING/STOR	AGE RELATIVE HUMIDITY		20%	÷ 90% RH (non-conder	nsing)		
APPROVALS			CE cULus Listed				





QT3400/3600 & HT3400/3600



- TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel[®] Celeron[®], Core[™] i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors µUPS, with 512kB MRAM for retentive data management (optional)
- Available in SO, S1 and S2 version, with possibility to install additional interfaces, PCI/PCIe expansion slots and extractable drives slots for 2,5" SSDs/HDDs
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

GALLERY



QT3400/3600 & HT3400/3600 - (S0 Version)



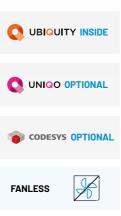
QT3400/3600 & HT3400/3600 - (D2 Version)

DETAIL - EXTRACTABLE DRIVES SLOT



COMPARISON TABLE

	QT3400/3600 & HT3400/3600					
	S0	S1	D2			
ADD-ON INTERFACES (optional)	\checkmark	\checkmark	\checkmark			
EXPANSION SLOTS PCI/PCIe	×	1	×			
INTERNAL INSTALLATION KIT for SSDs/HDDs 2,5" SATA III	1	1	×			
EXTRACTABLE DRIVES SLOT for SSDs/HDDs 2.5" SATA III	×	×	2			



RVL

QT3400/3600 & HT3400/3600 - (S1 Version)

QT3400/3600 & HT3400/3600

TECHNICAL DATA

		QT3400/3600 -ALU	QT3400/3600 -TFM	HT3400/3600 -ALU	HT3400/3600 -TF	HT3400/3600 -TFX	HT3400/3600 -TFM
LED BACKLIGHT TFT LCD		15.6″ W - 1 18.5″ W - 18.5″ W - 1 21.5″ W - 1	1366x768 1920x1080 1366x768 1920x1080 1920x1080 320x1080	15.6" W - 1366x768 12. 15.6" W - 1920x1080 15. 17" - 1280x1024 17"		12.1" - 800×600 12.1" - 1024×768 15.0" - 1024×768 17" - 1280×1024 19" - 1280×1024	12.1" W - 1280x800 (not for D2 version) 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080
CUT-OUT		Ç)T			HT	
FRONT USB			-	1 x USB 2.0 (Typ	e-A), protected		
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires	3	P-CAP Multitouch
FRONT PANEL	Material	Aluminium	True Flat Aluminium	Aluminium	True Flat Aluminium	True Flat Stainless Steel	True Flat Aluminium
	ASEM Logo		-	Adhesive label	Silk-scre	en printed	-
PROTECTION	IP rating		IP65 - f	frontal IP66K - fronta			IP65 - frontal
GRADE	NEMA rating	UL Type 1, 4x	UL Type 1, 4x (indoor only) UL Type 1, 4x (indoor only) and 1			indoor only) and 12	
0405	Installation	Panel mounting					
CASE	Material			Zinc-coated	skin pass steel		
PROCESSOR (soldered	xx3400	Intel® Celeron® G3900E 2.40GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ 13-6100E 2.70GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ 15-6440EQ 2.70GHz (3.40GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ 17-6820EQ 2.80GHz (3.50GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm				14nm rt cache • 14nm	
on-board)	xx3600	Intel® Core™ i3-7100E 2.90GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7440EQ 2.90GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-7820EQ 3.00GHz (3.70GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm					rt cache • 14nm
CHIPSET	xx3400	Intel® HM170 PCH (Platform Controller Hub) with integrated RAID controller					
	xx3600		Intel® HM175 PCH (Platform Controlle	er Hub) with integr	ated RAID controll	er
VIDEO CONTROLLER	xx3400	Int	el® HD Graphics 53	0 integrated in Int	el® Core™ i3 proce	essor • 350MHz/950 essor • 350MHz/950 rocessors • 350MH	MHz
CONTROLLER	xx3600					essor • 350MHz/950 rocessors • 350MH	
WATCHDOG				Programmab	ole time period		
ТРМ			Intel® PTT (TR	PM integrated) • Di	screte TPM 2.0 m	odule (optional)	
SYSTEM MEMORY RAM		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)					
	Cfast		1x bootable CFast	SATA III slot onboa	ard with external a	access (up to 240G	3)
MASS STORAGE	SSD mSATA	1x	onboard connecto	or for direct inserti	on of SSD mSATA	SATA III (up to 960	GB)
	SSD/HDD		1x onboard connec	tor for SSD/HDD 2	,5″ SATA III with in	ternal installation	kit
EXTRACTABLE Mass storage	only D2 version		2x (extractable SSDs/	HDDs 2.5″ SATA III	units	
RAID				Rai	d 0, 1		

TECHNICAL DATA

		QT3400/3600 -ALU	QT3400/3600 -TFM	HT3400/3600 -ALU	HT3400/3600 -TF	HT3400/3600 -TFX	HT3400/3600 -TFM		
	LAN	4x Gigabit Ethernet (RJ45)							
INTERFACES	USB		3)	k USB 3.0 (Type-A)	• 2x USB 2.0 (Type	e-A)			
INTERFACES	SERIAL			1x RS23	2 (DB9M)				
	VIDEO			1x DVI-D (Resoluti	on up to 1920x108	0)			
ADD-ON	Position A (max 1)								
(optional)	Position B (max 1)	and/	1x or 2x RJ45 connectors for RVL 1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)						
EXPANSION SLOTS	only S1 version		1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W						
POWER SUPPLY INF	TUT			24VDC (18÷3	2VDC) isolated				
POWER SUPPLY	UPS	UPS with external battery pack (Pb • 12V/2.5Ah) (backside or separate mounting)							
(optional)	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)							
BATTERY				1x CR2032 Ir	iternal access				
0.S. CERTIFIED	xx3400	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 32/64 bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit							
	xx3600		Microso	ft Windows 10 IoT	Enterprise 2019/2	2016 64 bit			
OPERATING TEMPERATURE	without forced ventilation		0°C÷4	45°C (24x7 HDD or	÷ 50°C Intel© Core™ i7 pro Standard HDD)	ocessor)			
STORAGE TEMPERA	TURE			-10°C	÷60°C				
OPERATING/STORA	GE RELATIVE HUMIDITY			20% ÷ 90% RH (non-condensing)				
APPROVALS		CE CE CE CE CE CULus Listed ATEX zone 2/22							

1. Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.

QT3500 & HT3500



• TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 12.1", 15.6", 18.5", 21.5", 24" in Wide aspect ratio

FANLESS

- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel® Celeron®, Core™ i3, i5, i7 processors of Kaby Lake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with one PCI or PCIe expansion slot
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

GALLERY



QT3500 & HT3500 - (SL Version)



QT3500 & HT3500 - (S1 Version)

DETAIL - EXPANSION SLOTS





QT3500 & HT3500 - (S0 Version)

1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W (only S1 version)

QT3500 & HT3500

TECHNICAL DATA

		QT3500-ALU	QT3500-TFM	HT3500-ALU	HT3500-TF	HT3500-TFM	HT3500-TFX
LED BACKLIGHT TFT LCD		15.6″ W - 18.5″ W - 18.5″ W - 21.5″ W -	- 1366x768 1920x1080 - 1366x768 1920x1080 1920x1080 1920x1080	12.1" - 800x600 12.1" - 1024x768 12.1" W - 1280x800 15" - 1024x768 15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1360x768 18.5" W - 1920x1080 19" - 1280x1024 21.5" W - 1920x1080 24"W - 1920x1080		12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24"W - 1920x1080	12.1″ - 800x600 12.1″ - 1024x768 15″ - 1024x768 17″ - 1280x1024 19″ - 1280x1024
CUT-OUT			О Т			HT	
FRONT USB			-	1 x USB 2.0 (Typ	e-A), protected	-	
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch	Resistive	5 wires	P-CAP Multitouch	Resistive 5 wires
FRONT PANEL	Material	Aluminum	True Flat Aluminum	Aluminum	True Fl	at Aluminum	True Flat Stainless Steel
	ASEM Logo		-	Adhesive label	Adhesive label Silk-screen printed		Silk-screen printed
PROTECTION	IP rating			IP65 - frontal			IP66K - frontal
GRADE	NEMA rating	UL Type 1, 4	x(indoor only)		UL Type 1, 4x	(indoor only) and 12	
CASE	Installation			Pane	Imounting		
CAGE	Material			Zinc coate	d stainless steel		
PROCESSOR (solde	red on-board)	Intel® Celeron® 3965U 2.20GHz 64bit• 2 cores / 2 threads• 2MB Smart cache• 14nm Intel® Core™ i3-7100U 2.40GHz 64bit• 2 cores / 4 threads• 3MB Smart cache• 14nm Intel® Core™ i5-7300U 2.60GHz (3.50GHz Turbo) 64bit• 2 cores / 4 threads• 3MB Smart cache• 14nm Intel® Core™ i7-7600U 2.80GHz (3.90GHz Turbo) 64bit• 2 cores / 4 threads• 4MB Smart cache• 14nm					
CHIPSET		Inte	el® Kaby Lake U PC	H (Platform Contro	oller Hub)• Includ	ed into processor chip	(SoC)
VIDEO CONTROLLE	R	Intel® HD Graphics 610 integrated in Intel® Celeron® processor• 300MHz/900MHz Intel® HD Graphics 620 integrated in Intel® Core™ i3 processor• 300MHz/1GHz Intel® HD Graphics 620 integrated in Intel® Core™ i5 processor• 300MHz/1.10GHz Intel® HD Graphics 620 integrated in Intel® Core™ i7 processor• 300MHz/1.15GHz					
WATCHDOG				Programm	able time period		
ТРМ	Discrete version only for SO/S1 versions and BM		Intel® PTT (TPM integrated) • I	Discrete TPM 2.0	module (optional)	
SYSTEM MEMORY R	AM		4GB or 8GB or 16GB (1x SODIMM DDR4 module)				
	Cfast		1x bootable CFas	st SATA III slot onb	oard with externa	al access (up to 240GB)
MASS STORAGE	SSD M.2	1x onboard co		insertion of M.2 2 D (up to 1TB) ¹ or M		2 SSD (up to 512GB) or SSD (up to 480GB)	M.2 2280 NVMe
	SSD/HDD only SO/S1 versions and BM		1x onboard conne	ector for SSD/HDD	2.5″ SATA III with	n internal installation k	t
	LAN			3x Gigabit	Ethernet (RJ45)		
INTERFACES	USB			4x USB	3.0 (Type-A)		
	SERIAL			1x RS2	232 (DB9M)		
	VIDEO			1x Displa	ayPort++ V1.2		
ADD-ON INTERFACES	Position A (max 1)						
(optional) not available for SL version	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x DVI-D (Resolution up to 1900x1200) 1x RJ45 connector for RVL 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz• Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)					

TECHNICAL DATA

		QT3500-ALU	QT3500-TFM	HT3500-ALU	HT3500-TF	HT3500-TFM	HT3500-TFX
EXPANSION SLOTS	only S1 version		1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W				
POWER SUPPLY INF	тит			24VDC (18÷	32VDC) isolated		
UPS With external battery pack (Pb• 12V/2.5A) (backside or separate mounting)							
(optional)	ATX only S0/S1 versions	Kit for ALX mode nower supply (push button internal cable and connector for remote cont					ote control)
BATTERY		1x CR2032 internal access					
0.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit					
OPERATING TEMPE	RATURE	0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)					
STORAGE TEMPERA	TURE	-10°C ÷ 60°C					
OPERATING/STORA	GE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)					
APPROVALS		CE cULus Listed					
1 The M 2 NV/Me F	PCIe v4 SSDs show actual n	orformonoo that		an ufa atuma da alait			

1. The M.2 NVMe PCIe x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCIe x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCIe x2 SSDs).

QT5400/5600 & HT5400/5600



- TFT LCDs in 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio and 15.6", 18.5", 21.5", 24" in Wide aspect ratio
- Aluminum (ALU) and aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFX) front panels with resistive touchscreen
- Intel[®] Celeron[®], Core[™] i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- · Available in SO version with the possibility to install additional interfaces, S1 version with one PCIe expansion slot and S3 version with three PCIe expansion slots
- Available with additional RVL interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)
- Available with 115/230VAC power supply (optional)

GALLERY



QT5400/5600 e HT5400/5600 - (S0 Version) - 24VDC



QT5400/5600 e HT5400/5600 - (S1 Version) - 24VDC



QT5400-5600, HT5400-5600 - (S3 Version) - 24VDC

DETAIL - EXTRACTABLE DRIVES SLOT







QT5400/5600 e HT5400/5600 - (S0 Version) - 230VAC



QT5400/5600 e HT5400/5600 - (S1 Version) - 230VAC



QT5400-5600, HT5400-5600 - (S3 Version) - 230VAC

QT5400/5600 & HT5400/5600

TECHNICAL DATA

LED BACKLIGHT IS-S' V - 1380-788 5 F. W - 1920-7080 5 F. W - 1920-7080 18 S. W - 1920-7080 19 S. W - 1920-7080 27 W - 1920-7080 20 W - 1920-7080 20 W - 1920-7080 20 W - 1920-7080 20 W -			QT5400/5600 -ALU	QT5400/5600 -TFM	HT5400/5600 -ALU	HT5400/5600 -TF	HT5400/5600 -TFX	HT5400/5600 -TFM
FRONT USB tx USB 2.0 (Type-A). protected TOUCHSCREEN Resistive 5 wires P-CAP Putiti- touch Resistive 5 wires P-CAP Putiti- touch Resistive 5 wires P-CAP Putiti- touch Resistive 5 wires P-CAP Putition Auminum True Flat Auminum True Flat Auminum <td< th=""><th></th><th></th><th>15.6″ W - 1 18.5″ W - 18.5″ W - 1 21.5″ W - 1</th><th>1920x1080 1366x768 1920x1080 1920x1080</th><th colspan="2">15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1920x1080 19" - 1280x1024 21.5" W - 1920x1080</th><th>17" - 1280x1024</th><th>15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080</th></td<>			15.6″ W - 1 18.5″ W - 18.5″ W - 1 21.5″ W - 1	1920x1080 1366x768 1920x1080 1920x1080	15.6" W - 1366x768 15.6" W - 1920x1080 17" - 1280x1024 18.5" W - 1366x768 18.5" W - 1920x1080 19" - 1280x1024 21.5" W - 1920x1080		17" - 1280x1024	15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080
TOUCHSCREEN Resistive 5 wires P-CAP Multi- touch Resistive 5 wires P-CAP Multiouch FRONT PANEL Material Aluminum True Flat Aluminum	CUT-OUT		Ç	T			HT	
IOUCRECKEEN wires touch Heisitive Sum 2000 PCAP Multicon FRONT PANEL Material Aluminum True Flat Aluminum True Flat	FRONT USB			-	1x USB 2.0 (Typ	e-A), protected		-
PRONT PANEL Memory Aluminum Aluminum Aluminum Stainless Steel Inde Fad Aluminum PROTECTION MP rating IPBS - Frontal Sike sur-emprinted - PROTECTION MP rating IPBS - Frontal	TOUCHSCREEN					Resistive 5 wires		P-CAP Multitouch
PROTECTION GRADE IP rating IP65 - frontal IP66 K - frontal IP66 K - frontal CASE Installation Panel mounting CASE Installation Panel mounting PROCESSOR (soldered) Material Zinc-coated skin pass steel Intel® Core® 7.500.3.200Hz (Jubbit -4 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.3.70012.3.000Hz (Jubbit -4 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads - 3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads -3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads -3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -2 cores / 4 threads -3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -4 cores / 4 threads -3MB Smart cache - 14mm Intel® Core® 7.7.700.3.3.00Hz (Jubbit -4 cores / 4 threads -3MB Smart cache - 14mm CHIP	FRONT PANEL	Material	Aluminum		Aluminum			True Flat Aluminum
PROTECTION NEMA rating UL Type 1, 4x (indoor only) UL Type 1, 4x (indoor only) and 12 CASE Installation Panel mounting CASE Material Zinc-coated skin pass steel PROCESSOR (soldered on-board) XS5400 Intel® Core® 13-BID 3.70GHz 24bit - 2 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-B700 3.40GHz (14.00GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-B700 3.40GHz (14.00GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-B700 3.40GHz (14.00GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.40GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.40GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-F700 3.50GHz (14.20GHz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache + 14n		ASEM Logo		-	Adhesive label	Silk scree	en printed	-
CASE Installation Complexity Complexity Complexity CASE Material Zane-coated skin pass steel PROCESSOR (soldered on-board) intel® Core® 15-600 3.200Hz (2400Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 15-600 3.200Hz (2400Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-6700 3.400Hz (2400Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-6700 3.400Hz (2400Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-7700 3.800Hz (2400Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-7700 3.800Hz (2.800Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-7700 3.800Hz (2.800Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm CHIPSET Intel® Core® 17-7700 3.800Hz (2.800Hz turbo) 640H + 4 cores / 4 threads • 6HB Smart cache • 14mm Intel® Core® 17-7700 3.800Hz (2.800Hz turbo) 640H + 4 cores / 8 threads • 8HB Smart cache • 14mm VIDEO CONTROLLER xx5400 Intel® HD Graphics 500 integrated in Intel® Core® 13 and 15 processors • 350HHz/1.106Hz VIDEO CONTROLLER xx5400 Intel® HD Graphics 630 integrated in Intel® Core® 13 and 15 processor • 350HHz/1.106Hz VIDEO CONTROLLER Xx5400 Intel® HD Graphics 630 integrated in Intel® Core® 13 and 15 processor • 350HHz/1.106Hz SYSTEM MEMORY RM (soldered) Intel® HD Graphics 50 integrated in Intel® Core® 13 and 15 processor • 350HHz/1.106Hz SYSTEM MEMORY RM (soldered)	PROTECTION	IP rating		IP65 -	frontal		IP66K - frontal	IP65 - frontal
CASE Material Zinc-coated skin pass steel PROCESSOR (coldered on-board) xx56400 Intel® Core® 15-500 3.20GHz 54,01 - 2 cores / 4 threads - 3MB Smart cache - 14nm Intel® Core® 15-500 3.20GHz (4.00GHz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-500 3.20GHz (4.00GHz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.00GHz (4.00GHz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.00GHz (4.00GHz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.00GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 5 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.40GHz (3.00Hz + 1urbo) 64bit - 4 cores / 5 threads - 8MB Smart cache - 14nm Intel® Core® 15-700 3.50GHz (3.00Hz + 1urbo) 64bit - 4 cores / 5 threads - 8MB Smart cache - 14nm VIDEO CONTROLLER xx5600 Intel® HD Graphics 500 integrated in Intel® Core® 15 processor - 350MHz/1.15GHz Intel® HD Graphics 630 integrated in Intel® Core® 17 processor - 350MHz/1.15GHz Intel® HD Graphics 630 integrated in Intel® Core® 17 processor - 350MHz/1.15GHz WATCHDOC Programmable time period Ymbos X tesosoble KB S0DIMM DDR M module)	GRADE	NEMA rating	UL Type 1, 4x	(indoor only)		UL Type 1, 4x (indoor only) and 1	2
Intel® Core® 13-6003 7.00Hz 64bit - 2 cores / 4 threads - 3MB Smart cache - 14nm Intel® Core® 13-6003 7.00Hz 64bit - 2 cores / 4 threads - 3MB Smart cache - 14nm Intel® Core® 17-6700 3.400Hz (3.60Hz + 10tho) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-6700 3.400Hz (4.000Hz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 17-6700 3.400Hz (4.000Hz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz Turbo) 64bit - 4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7003 3.400Hz (1.000Hz - 4 threads - 8MB Smart cache + 14nm VIED0 <th>0405</th> <th>Installation</th> <th></th> <th></th> <th>Pane</th> <th>mounting</th> <th></th> <th></th>	0405	Installation			Pane	mounting		
PROCESSOR (soldered) intel® Core® 15-6500 3.20GHz (3.60GHz Turbol 6kbit -4 cores / 4 threads - 6MB Smart cache - 14nm Intel® Core® 17-7000 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7000 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7000 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7000 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 4 threads - 8MB Smart cache - 14nm Intel® Core® 15-7000 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 7 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 7 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 7 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 7 8 threads - 8MB Smart cache - 14nm Intel® Core® 17-7700 3.40GHz (4.00GHz Turbol 6kbit -4 cores / 7 8 mol 5 processors - 350MHz/1.10GHz Intel® HD Graphics 50 integrated in Intel® Core® 13 and 15 processors - 350MHz/1.10GHz Intel® HD Graphics 60 integrated in Intel® Core® 17 processors - 350MHz/1.10GHz Intel® HD Graphics 60 integrated in Intel® Core® 17 processors - 350MHz/1.10GHz Intel® HD Graphics 50 integrated in Intel® Core® 17 processors - 350MHz/1.10GHz Intel® HD Graphics 50 integrated in Intel® Core® 13 and 15 processors - 350MHz/1.10GHz Intel® HD Graphics 50 integrated in Intel® Core® 13 and 15 processors - 350MHz/1.10GHz Intel® HD Graphics 50 integrated in Intel® Core® 13 and 15 processors - 350MHz/1.10GHz Intel® HD Graphics 50 Integrated in Intel® Core® 13 and 15 processors - 350MHz/1.10GHz Intel® HD Graphics 50 Integrated in In	CASE	Material			Zinc-coate	d skin pass steel		
on-board) xx6600 Intel® Core® i3-70E3.900b2.64bit -2.00res /2.40reads -240ES 2470 Sinal cache - 14mm Intel® Core® i3-70E3.900b2.64bit -2.00res /4.40reads -340E Smart cache - 14mm Intel® Core® i3-70E3.900b2.64bit -2.00res /4.40reads -640E Smart cache - 14mm CHPSET Intel® Core® i3-70E3.900b2.64bit -2.00res /4.40reads -640E Smart cache - 14mm VIDEO xx5400 Intel® Core® i3-70E3.900b2.64bit -2.00res /4.40reads -640E Smart cache - 14mm VIDEO xx5400 Intel® Core® i3-70E3.900b2.64bit -2.00res /1.40reads -640E Smart cache - 14mm VIDEO xx5400 Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors -350MHz/1.05GHz VIDEO xx5600 Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors -350MHz/1.06Hz VIDEO xx5600 Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors -350MHz/1.06Hz VIDEO xx5600 Intel® HD Graphics 530 integrated in Intel® Core® i7 processors -350MHz/1.06Hz VIDEO xx5600 Intel® HD Graphics 530 integrated in Intel® Core® i7 processor -350MHz/1.06Hz VIDEO xx5600 Intel® PTT(TPM integrated) Discrete TPM 2.0 module (optional) System MEMORY RAM (soldered) Soldered Sold XGB SODIMM DDR4 module) Syster X = Sononz Sonopze Connector for direct insert	PROCESSOR	xx5400	Intel® Core™ i5-6500 3.20GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm					
VIDEO CONTROLLER xx5400 Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.05GHz Intel® HD Graphics 530 integrated in Intel® Core® i7 processor • 350MHz/1.06Hz WATCHDOG Intel® HD Graphics 630 integrated in Intel® Core® i3 and i5 processor • 350MHz/1.06Hz Intel® HD Graphics 630 integrated in Intel® Core® i3 and i5 processor • 350MHz/1.06Hz WATCHDOG Programmable time period TPM Intel® PTT (TPM integrated) - Discrete TPM 2.0 module (optional) SYSTEM MEMORY RAM (soldered) Intel® Core® i2 and i5 processor • 350MHz/1.15GHz MASS STORAGE Cfast 1x bootable CFast SATA III solt on board with external access (up to 240GB) MASS STORAGE SSD/HDD 2x onboard connector for SSDS/HDD 2.5" SATA III with internal installation kit EXTRACTABLE RAID SO/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III units RAID Raid 0, 1 Raid 0, 1 INTERFACES LAN 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0(Type-A) 1x RS232(DBSM)	on-board)		Intel® Core™ i3-7101E 3.90Ghz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7500 3.40Ghz (3.80GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm					
VIDEO CONTROLLERXX5400Intel® HD Graphics 530 integrated in Intel® Core® i7 processor • 350MHz/1.15GHzVIDEO CONTROLLERXX5600Intel® HD Graphics 610 integrated in Intel® Core® i7 and 15 processor • 350MHz/1.00GHz Intel® HD Graphics 630 integrated in Intel® Core® i7 processor • 350MHz/1.15GHzWATCHD0G TPMOPogrammable time periodSYSTEM MEMORY RAW (soldered)Intel® HD Graphics 630 integrated in Intel® Core® 10 module (optional)SYSTEM MEMORY RAW (soldered)AGB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module)MASS STORAGE MASS STORAGESSD H21x botoard connector for direct insertion SSD (1x 0x 480GB)RAIDSO/SI/S3 versions only SI/S3 versions1x extractable SSD/HDD 2.5' SATA III with internal installation kit 1x extractable SSD/HDD 2.5' SATA III with 1x extractable S	CHIPSET		Intel® C236 PCH (Platform Controller Hub) with integrated RAID controller					
CONTROLLER xx5600xx5600Intel® HD Graphics 610 integrated in Intel® Celeron® processor • 350 MHz/1.10GHz Intel® HD Graphics 630 integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core® 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 MHz/1.10GHz Intel® HD Graphics 630 Integrated in Intel® Core 0 17 processor • 350 Mz Integrated in Intel® Core 0 17 processor • 350 MIZ · 4006BMASS STORAGES0D/HD S0J/SI · S0D · A 100 Si S/S3 VersionsI x extractable SSD / HDD 2.5' SATA III units<		xx5400						
TPM Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional) SYSTEM MEMORY RAM (soldered) 4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module) MASS STORAGE Cfast 1x bootable CFast SATA III slot onboard with external access (up to 240GB) MASS STORAGE SSD H.2 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III SSD (up to 480GB) MASS STORAGE SO/S1/S3 versions 1x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit EXTRACTABLE MASS STORAGE SO/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III unit RAID Raid 0, 1 Raid 0, 1 INTERFACES USB 4x USB 3.0 (Type-A) INTERFACES SERIAL 1x RS232 (DB9M)		xx5600	Intel® HD Graphics 630 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.10GHz					
SYSTEM MEMORY RAM (soldered) 4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module) MASS STORAGE Cfast 1x bootable CFast SATA III slot onboard with external access (up to 240GB) MASS STORAGE SSD M.2 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III SSD (up to 480GB) EXTRACTABLE MASS STORAGE S0/S1/S3 versions 1x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit EXTRACTABLE MASS STORAGE S0/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III unit RAID S0/S1/S3 versions 2x extractable SSDs/HDDs 2.5" SATA III units RAID LAN 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) 1x RS232 (DB9M)	WATCHDOG				Programma	able time period		
SYSTEM MEMORY RM (soldered) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module) MASS STORAGE Cfast 1x bootable CFast SATA III slot onboard with external access (up to 240GB) MASS STORAGE SSD H.2 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III MASS STORAGE SSD/HDD 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III EXTRACTABLE MASS STORAGE SO/S1/S3 versions 1x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit RAID SO/S1/S3 versions 1x extractable SSDs/HDDs 2.5" SATA III units RAID LAN 4x Gigabit Ethernet (RJ45) USB USB 4x USB 3.0(Type-A) INTERFACES SERIAL 1x RS232 (DB9M)	ТРМ			Intel® PTT (1	[PM integrated) • [Discrete TPM 2.0 r	nodule (optional)	
MASS STORAGE SSD M.2 1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III SSD (up to 480GB) SSD/HDD SSD/HDD 2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit EXTRACTABLE MASS STORAGE S0/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III with internal installation kit RAID Conly S1/S3 versions 2x extractable SSDs/HDDs 2.5" SATA III units RAID LAN 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) INTERFACES SERIAL Ix RS232 (DB9M)	SYSTEM MEMORY R	AM (soldered)			8GB (2x 4GB SO 16GB (2x 8GB SO	DIMM DDR4 modu DIMM DDR4 modu	ile) ile)	
MASS STURAGE SSD H.2 SSD/HDD SSD (up to 480GB) SSD/HDD 2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit EXTRACTABLE MASS STORAGE S0/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III unit only S1/S3 versions 2x extractable SSD/HDD 2.5" SATA III units RAID 2x extractable SSDs/HDDs 2.5" SATA III units INTERFACES LAN 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) Ix RS232 (DB9M) 1x RS232 (DB9M)		Cfast		1x bootable CFas	t SATA III slot onb	oard with external	access (up to 240)GB)
S0/S1/S3 versions 1x extractable SSD/HDD 2.5" SATA III unit MASS STORAGE only S1/S3 versions 2x extractable SSDs/HDDs 2.5" SATA III units RAID Raid 0, 1 INTERFACES USB 4x Gigabit Ethernet (RJ45) SERIAL 1x RS232 (DB9M)	MASS STORAGE	SSD M.2	2				or M.2 2242 SATA III	
EXTRACTABLE Only S1/S3 versions 2x extractable SSDs/HDDs 2.5" SATA III units RAID Raid 0, 1 INTERFACES USB 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) Ix RS232 (DB9M)		SSD/HDD	2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit					
RAID Compositions Exercisions INTERFACES USB 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) Ix RS232 (DB9M)	EXTRACTABLE	S0/S1/S3 versions	1x extractable SSD/HDD 2.5" SATA III unit					
INTERFACES LAN 4x Gigabit Ethernet (RJ45) USB 4x USB 3.0 (Type-A) SERIAL 1x RS232 (DB9M)	MASS STORAGE	only S1/S3 versions	2x extractable SSDs/HDDs 2.5" SATA III units					
INTERFACES USB USB USB 4x USB 3.0 (Type-A) 1x RS232 (DB9M)	RAID		Raid 0, 1					
INTERFACES SERIAL 1x RS232 (DB9M)		LAN	AN 4x Gigabit Ethernet (RJ45)					
SERIAL 1x RS232 (DB9M)		USB			4x USB	3.0 (Type-A)		
VIDEO 1x DVI-D (Resolution up to 1920x1080)	INTERFACES	SERIAL			1x RS	232 (DB9M)		
		VIDEO			1x DVI-D (Resolu	tion up to 1920x10	80)	

TECHNICAL DATA

		QT5400/5600 -ALU	QT5400/5600 -TFM	HT5400/5600 -ALU	HT5400/5600 -TF	HT5400/5600 -TFX	HT5400/5600 -TFM	
ADD-ON	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)						
INTERFACES (optional)	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x or 2x RJ45 connectors for RVL 2x DisplayPort++ V1.2 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)						
EXPANSION	only S1 version		1x	PCIe x16 half-lengt	h, on riser card, n	nax 50W		
SLOTS	only S3 version	1x PCIe x16 half-length + 1xPCIe x4 half-length + 1xPCIe x1 half-length or 2x PCIe x8 half-length + 1x PCIe x4 half-length, on riser card, max 50W total					length + 1x PCIe x4	
POWER SUPPLY				24VDC (18÷	32VDC) isolated			
INPUT	optional	115V/230VAC (85÷264VAC) isolated, autoranging						
POWER SUPPLY (optional)	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)						
BATTERY		1x CR2032 Internal access						
0.S. CERTIFIED	xx5400	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 64 bit Microsoft Windows Embedded Standard 7E/7P 64 bit Microsoft Windows Server Embedded Standard 2019 R2 64 bit						
	xx5600	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows Server Embedded Standard 2019 R2 64 bit						
OPERATING TEMPER	RATURE	0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)						
STORAGE TEMPERA	TURE	-10°C ÷ 60°C						
OPERATING/STORA	GE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)						
APPROVALS	APPROVALS CE cULus Listed							

COMPARISON **TABLE**

		QT2150 & HT2150	QT2200 & HT2200	QT2250 & HT2250	QT3400 & HT3400	QT3500 & HT3500	QT3600 & HT3600	QT5400 & HT5400	QT5600 & HT5600
FANLESS		\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	X	X
Wide sizes	7", 10,1", 12,1", 15,6"	10,1", 12,1", 15,6", 18,5", 21,5", 24"	7", 10,1", 12,1", 15,6", 18,5", 21,5", 24"	12,1", 15,6", 18,5", 21,5", 24″	12,1", 15,6", 18,5", 21,5", 24″	12,1", 15,6", 18,5", 21,5", 24″	15,6", 18,5", 21,5", 24"	15,6", 18,5", 21,5", 24"	
FRONT	Narrow sizes	8,4", 10,4", 12,1", 15"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"	10,4", 12,1", 15", 17", 19"
PANELS	Types	ALU, TF, TFM	ALU, TF, TFM, TFX	ALU, TF, TFM, TFK	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX	ALU, TF, TFM, TFX
	Touchscreen technology	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch	Resistive Multitouch
PROCESSORS	Model	Intel® Celeron® J1900	Intel® Celeron® J1900	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel® Celeron® G3900E Intel® Core™ i3-6100E Intel® Core™ i5-6440EQ Intel® Core™ i7-6820EQ	Intel® Celeron® 3965U Intel® Core™ i3-7100U Intel® Core™ i5-7300U Intel® Core™ i7-7600U	Intel® Core™ i3-7100E Intel® Core™ i5-7440E0 Intel® Core™ i7-7820E0	Intel® Core™ i3-6100 Intel® Core™ i5-6500 Intel® Core™ i7-6700	Intel® Celeron® G3930E Intel® Core™ i3-7101E Intel® Core™ i3-7101E Intel® Core™ i7-7700
	Generation	Intel® Bay Trail	Intel® Bay Trail	Intel® Apollo Lake	Intel® Skylake	Intel® Kaby Lake U	Intel® Kaby Lake	Intel® Skylake	Intel® Kaby Lake
SYSTEM MEMO	RY	Up to 8GB	Up to 8GB	Up to 8GB	Up to 32GB	Up to 16GB	Up to 32GB	Up to 32GB	Up to 32GB
	LAN	2x RJ45	2x RJ45	2x RJ45	4x RJ45	3x RJ45	4x RJ45	4x RJ45	4x RJ45
	USB	1x USB 3.0 • 1x USB 2.0	2x USB 2.0 • 1x USB 3.0	3x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	4x USB 3.0
INTERFACES	Serial	-	1x RS232 (DB9M)	-	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)
	Video	-	1x DVI-D	1x DisplayPort++ V1.2	1x DVI-D	1x DisplayPort++ V1.2	1x DVI-D	1x DVI-D	1x DVI-D
EXPANSION SL	OTS PCI/PCIe	-	Up to 1	-	Up to 1	Up to 1	Up to 1	Up to 3	Up to 3
INTERNAL SSD)/HDD	-	Up to 1	-	Up to 1	Up to 1	Up to 1	Up to 3	Up to 3
EXTRACTABLE	E SSD/HDD	-	-	-	Up to 2	-	Up to 2	Up to 2	Up to 2
POWER SUPPL	Y INPUT	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC 115V/230VAC	24VDC 115V/230VAC
OPERATING SY	'STEMS	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC Microsoft Windows Server Embedded Standard	Microsoft Windows 10 IoT Enterprise LTSC Microsoft Windows Server Embedded Standard
PAC VERSION *	×	X	\checkmark	X	\checkmark	X	\checkmark	X	X
CERTIFICATION	vs	C E CUL	$C \in \operatorname{cup}_{usted} us \langle E_{X} \rangle^{**}$		$C \in \operatorname{c}_{LSTED}^{U} \operatorname{us} \operatorname{Ex}^{**}$	C E CULUS	C C C C LISTED US C X	C E CULUSTED	C E CULUS

* with UPS + 512kB MRAM for retentive data management and Codesys software ** only for QT-TFM





BOX IPCS

HIGH PERFORMANCE **ROBUST DESIGN**

PB2150 & BM2150



FANLESS

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- Intel[®] Celeron[®] processor of SoC Bay Trail generation
- RAM up to 8GB
- DIN rail mounting available (only BM2150)
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth and SO version with the possibility to install additional interfaces (only PB2150)

TECHNICAL DATA

		PB2150	BM2150		
PROTECTION	IP rating	IP20			
GRADE	NEMA rating	-	-		
	Installation	Wall mounting	Book/DIN mounting		
CASE	Material	Zinc-coated skin pass steel	Aluminum alloy		
PROCESSOR (solde	ered on-board)	Intel® Celeron® J1900 2.00Ghz (2.30GHz Burs	t)•4 cores / 4 threads • 2MB L2 cache • 22nm		
CHIPSET		Intel® Bay Trail • Included	into processor chip (SoC)		
VIDEO CONTROLLE	R	Intel® HD Graphics for Intel Atom® proc	cessor Z3700 series • 688MHz/854MHZ		
SYSTEM MEMORY F	MAN	1GB or 2GB or 4GB or 8GE	3 SODIMM DDR3L module		
	CFast	1x bootable CFast SATA II slot onboar	d with external access (up to 240GB)		
MASS STORAGE	SSD mSATA	1 x onboard connector for direct inserti	on of mSATA SSD SATA II (up to 960GB)		
	LAN	2x Gigabit Eth	hernet (RJ45)		
INTERFACES	USB	1x USB 3.0 (Type-A)•	• 1x USB 2.0 (Type-A)		
	VIDEO	1 x DVI-D (Resolution	on up to 1920x1080)		
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM	1) IX USB 2.0 (Type-A) 2x USB 2.0 (Type-A)			
POWER SUPPLY IN	PUT	24VDC(18÷32VDC)isolated			
	UPS	UPS with external batte (separate	ry pack (Pb • 12V/2,5Ah) mounting)		
POWER SUPPLY (optional)	ATX only S0 version and BM w/o UPS	Kit for ATX mode power supply (push button, in	ternal cable and connector for remote control)		
	ATX only BM w/ UPS	-	Kit for ATX mode power supply (connector for remote control)		
BATTERY		1x CR2032 Int	ternal access		
Microsoft Windows 7 Pro/Ultimate 32/64bit 0.S. CERTIFIED Microsoft Windows Embedded Standard 7E/7P 32/64 bit Microsoft Windows 10 IoT Enterprise 2016/2019 64 bit Microsoft Windows 10 IoT Enterprise 2016/2019 64 bit			ed Standard 7E/7P 32/64 bit		
OPERATING TEMPE	ERATURE	0°C ÷ 50°C			
STORAGE TEMPER	ATURE	-5°C ÷ 60°C			
OPERATING/STOR	AGE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)			
APPROVALS		CE cULus Listed			

PB2200 & BM2200



CODESYS OPTIONAL

FANLESS

REMOTE

VIDEO LINK

- Intel[®] Celeron[®] processors of SoC Bay Trail generation
- RAM up to 8GB
- Built-in UPS with external battery pack (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with PCI or PCIe expansion slot (only PB2200)
- Available in RVL version (BM2200 RVL) for the remotation of the DVI-D and USB 2.0 signals up to 100m

TECHNICAL DATA

PROTECTION GRADE IP rating NEMA rating PROTECTION (NEMA rating) CASE Installation Wall mounting Material CASE Installation PROCESSOR (sold=row of Jigod 2.000 CHIPSET Intel® Celeron® Jigod 2.000 CHIPSET Intel® Celeron® Jigod 2.000 VIDEO CONTROLLER Ontel® HD Graphic VIDEO CONTROLLER 108 or 268 or 468 or 868 (tx 50 MASS STORAGE (SSD MSATA and SSD/HDD alter- native to each SSD/HDD atter- native to each SSD/HDD atter- native to each only SD/SI versions 1x onboard connect 1x onboard connect SSD/HDD atter- native to each SSD/HDD atter- sSD/HDD atter- sSD/HDD atter- native to each SSD/HDD atter- native to each SSD/HDD atter- sSD/HDD atter- sSD/HDD atter- NSD/SD/SD/SD/SD/SD/SD/SD/SD/S			
RADE NEMA rating CASE Installation Wall mounting PROCESSOR (soldered on-board) Intel® Celeron® J1900 2.006 CHIPSET Intel® Celeron® J1900 2.006 CHIPSET Intel® Celeron® J1900 2.006 CHIPSET Intel® Celeron® J1900 2.006 VIDEO CONTROLLER Intel® HD Graphic WATCHDOG Intel® HD Graphic SYSTEM MEMORY RAM IGB or 2GB or 4GB or 8GB (tx SO MASS STORAGE (SSD mSATA and SSD MSATA 1x onboard connection SSD/HDD anter- native to each other) SSD MSATA 1x onboard connection NTERFACES SERIAL 1x RS232 (DBS XSJ (HD) anter- native to each only SO/SI versions 1x DVI-1 (Resolution up to 1920 included) INTERFACES SERIAL 1x RS232 (DBS XSJ (22/4B5 (DB15M)) shi the XRS232 (DB15M) isolate 2x WS23 (DB15M) isolate 3x Wi-Fi module (IEEE 802.11 a/b) Bluetooth 4. and/or 1x Cellular module (word) contiser card, ma POWER SUPPLY INPUT VPS Ix PCI half-length or 1x PCI on riser card, ma Backside mounting not svailable for SL version Kit for ATX mode power sup internal cable and connector </th <th></th> <th></th> <th>PB2200</th>			PB2200
NETRY Fating Metry Fating CASE Installation Wall mounting PROCESSOR (soldered on-board) Intel® Celeron® J1900 2.006 CHIPSET Intel® Celeron® J1900 2.006 CHIPSET Intel® Material VIDEO CONTROLLER Intel® HD Graphic WATCHDOG Intel® MD Graphic SYSTEM MEMORY RAM 16B or 26B or 46B or 86B (hx 50 MASS STORAGE Cfast 1x bootable CFa SSD/HDD Inter- native to each other) SSD mSATA 1x onboard conner JUEE CONTROL SSD mSATA 1x onboard conner MASS STORAGE Cfast 1x onboard conner SSD/HDD Inter- native to each other) SSD mSATA 1x onboard conner JUE SSUMBAL SSD mSATA 1x onboard conner MASS STORAGE Cfast 1x RS232/422/48 (DB15M) +1 M INTERFACES SERIAL 1x RS232/422/48 (DB15M) +1 M (optional) Position A (max 1) 1x RS232/422/48 (DB15M) +1 M NKTERFACES Only S1 version 1x Gigabit Etherme 2x RS232 (DB15M) +1 M POWER SUPPLY INPUT V Ix Cellular module (wrdf GPRS, UM	PROTECTION	IP rating	
CASE Material Zinc-coated skin procession PROCESSOR (sold=red on-board) Intel® Celeron® J1900 2.000 CHIPSET Intel® Celeron® J1900 2.000 VIDEO CONTROLLER Intel® The PHD Graphic WATCHDOG Intel® Celeron® J1900 2.000 TPM IGB or 2GB or 4GB or 8GB (hr SO SYSTEM MEMORY RAM IGB or 2GB or 4GB or 8GB (hr SO MASS STORAGE Cfast 1x bootable CFa (SSD mSATA and SSD/HDD atter- native to each other) SSD mSATA 1x onboard conner NTERFACES SERIAL 1x RS232 (DBB 2x USB 2.0 (Type-A) + hr UD included) NTERFACES SERIAL 1x RS232 (DBB 2x USB 2.0 (Type-A) + hr UD included) ADD-ON INTERFACES Position A (max 1) 1x RS232/422/485 (DBHSM) + 1x RS232 (DBB 2x USB 2.0 (Type-A) + hr UD included) ADD-ON INTERFACES Position A (max 1) 1x RS232/422/485 (DBHSM) + 1x RS232 (DBB 2x USB 2.0 (Type-A) + hr UD included) 1x RS232 (DBB 2x USB 2.0 (Type-A) + hr UD 2x USB 2.0 (Type-A) + hr UD 2x USB 2.0 (Type-A) + hr UD 2x USB 2.0 (Type-A) + hr UD 3x USB 2.0 (Type-	GRADE	NEMA rating	
PROCESSOR (soldered on-board) Intel® Celeron® J1900 2.00G CHIPSET Intel® Celeron® J1900 2.00G VIDEO CONTROLLER Intel® HD Graphic WATCHDOG Intel® MD Graphic SYSTEM MEMORY RAM IGB or 2GB or 4GB or 8GB (ht SO MASS STORAGE (SSD mSATA and SSD/HDD alter- native to each other) SSD mSATA MASS STORAGE (SSD mSATA and SSD/HDD alter- native to each other) LAN INTERFACES LAN MADD-ON INTERFACES LAN ADD-ON INTERFACES Position A (max 1) NTERFACES Position A (max 1) Position A SL version N RS232/422/485 (DB15M) + 1 hx RS232/422/485 (DB15M) + 1	CASE	Installation	Wall mountir
CHIPSET Intel® VIDEO CONTROLLER Intel® HD Graphic WATCHDOG Intel® HD Graphic TPM IGB or 2GB or 4GB or 8GB (h SO SYSTEM MEMORY RAM IGB or 2GB or 4GB or 8GB (h SO MASS STORAGE (SSD mSATA and SSD/HDD alter- native to each other) SSD mSATA INTERFACES LAN USB 2x USB 2.0 (Type-A) + h.U. hx RS232 (DBS) INTERFACES SERIAL NDD-ON INTERFACES Position A (max 1) ADD-ON INTERFACES Position A (max 1) ADD-ON INTERFACES Position B (max 1) ADD-ON INTERFACES Position B (max 1) CEXPANSION SL version only S1 version POWER SUPPLY INPUT UPS Backside mounting not available for SL version POWER SUPPLY INPUT UPS with external battery pa (backside or separate or savailable for SL version POWER SUPPLY INPUT VIPS + 512kB MRAM Backside mounting not available for SL version POWER SUPPLY INPUT Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal Microox Micro BATTERY 1x CR2032 Internal Micro		Material	Zinc-coated skin p
VIDEO CONTROLLER Intel® HD Graphic WATCHDOG Intel® HD Graphic TPM IGB or 2GB or 4GB or 8GB (h SO SYSTEM MEMORY RAM IGB or 2GB or 4GB or 8GB (h SO MASS STORAGE (SSD mSATA and SSD/HDD alter- other) X bootable CFast 1x onboard connect SSD/HDD alter- other) SSD mSATA 1x onboard connect MASS STORAGE (SSD mSATA and SSD/HDD alter- other) SSD mSATA 1x onboard connect INTERFACES SERIAL 1x RS232 (DES INTERFACES SERIAL 1x RS232 (DES NITERFACES (optional) not available for SL version Position A (max 1) 1x RS232/422/485 (DB15M) + 1 1x RS232/422/485 (DB15M) + 2 2x USB 2.0 (Typ 2x USB 2.0	PROCESSOR (solde	red on-board)	Intel® Celeron® J1900 2.00G
WATCHDOG Interversion of the process of the proces	CHIPSET		Intel
TPM 1GB or 2GB or 4GB or 8GB (1x SO MASS STORAGE (SSD mSATA and SSD mSATA and SSD/HDD other) 1x bootable CFait 1x onboard connect SSD/HDD only SO/S1 versions INTERFACES LAN INTERFACES LAN USB 2x USB 2.0 (Type-A) + 1x US 0 (Typ	VIDEO CONTROLLE	R	Intel® HD Graphic
SYSTEM MEMORY RAM 1GB or 2GB or 4GB or 8GB (h x 50 MASS STORAGE (SSD mSATA and SSD mSATA 1x bootable CFa SSD/HDD alter- native to each other) SSD/HDD only SD/ST versions 1x onboard conner MASS STORAGE (SSD mSATA and SSD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each other) LAN 1x onboard conner MASS STORAGE (SD/HDD alter- native to each only SD/ST version 1x DVI-I (Resolution up to 1920 included) 1x RS232 (DBS 2x USB 2.0 (Type-A)-1x U 1x RS232 (DBS/HD) isolate 2x USB 2.0 (Type (SD/HD) ADD-ON INTERFACES (optional) not available for SL version 1x RS232 (DBS 2x USB 2.0 (Type (SPRS, UMTS/HSPA contro SL VERS UPS) 1x Gigabit Etherne 1x WI-Fi module (IEEE 802.11 a/b Bluetoth 4.2 and/or 1x Cellular module (world corriser card, ma only S1 version POWER SUPPLY INPUT UPS ackside mounting not available for SL version 1x PCI half-length or 1x PCI (backside or separate available for SL version POWER SUPPLY (optional) UPS +	WATCHDOG		
MASS STORAGE (SSD mSATA and SSD/HDD alter- native to each other) Cfast SSD mSATA SSD/HDD only SD/ST versions 1x bootable CFast Ix onboard connect sSD/HDD Ix onboard connect SSD/HDD Ix onboard connect SSD/HDD Ix onboard connect SSD/HDD Ix onboard connect Ix DV-HD USB INTERFACES LAN USB 1x USB 2.0 (Type-A)-1x US IX RS232/422/485 (DB15M) + 1 IX RS232/42/	TPM		
INSD of STATA and SSD/HDD alter- native to each other) SSD mSATA 1x onboard connect SSD/HDD INTERFACES SSD/SD/ST versions 1x onboard connect INTERFACES LAN 1x SSD mSATA INTERFACES SERIAL 1x SSD mSATA INTERFACES SERIAL 1x RS232/DBS VIDEO 1x DVI-I(Resolution up to 1920: included) 1x RS232/422/485 (DB15M) + 1 INTERFACES Position A (max 1) 1x RS232/422/485 (DB15M) + 1 ADD-ON INTERFACES Position A (max 1) 1x RS232/422/485 (DB15M) + 1 INTERFACES Position A (max 1) 1x RS232/422/485 (DB15M) + 1 INTERFACES Position B (max 1) 1x RS232/422/485 (DB15M) + 1 INTERFACES Position B (max 1) 1x RS232/422/485 (DB15M) + 1 INTERFACES Position B (max 1) 1x Wi-Fi module (IEEE 802.11 a/b Bluetooth 4.2 and/or 1x Cellular module (world GPRS, UMTS/HSPA c EXPANSION only S1 version 1x PCI half-length or 1x PCI on riser card, ma POWER SUPPLY INPUT UPS UPS with external battery pai (backside or separate (backside or separate (ba	SYSTEM MEMORY R	AM	1GB or 2GB or 4GB or 8GB (1x SO
SSD/HDD alter- native to each other) SSD mSATA Ix onboard connect sSD/HDD only SD/ST versions INTERFACES LAN INTERFACES SERIAL ADD-ON INTERFACES SERIAL ADD-ON INTERFACES VIDEO INTERFACES SERIAL INTERFACES VIDEO INTERFACES Position A (max 1) INTERFACES Position A (max 1) INTERFACES Position A (max 1) INTERFACES Position B (max 1) INTERFACES INTERFACES INTERFACES INTERE		Cfast	1x bootable CFa
other)Ix onboard connectonly S0/S1 versionsIx onboard connectINTERFACESLANUSB2x USB 2.0 (Type-A) • 1x USINTERFACESSERIALVIDEOIx DVI-I (Resolution up to 1920) included)ADD-ON INTERFACES (optional) not available for SL versionPosition A (max 1)POWER SUPPLY (optional)Position B (max 1)Backside mounting not available for SL versionUPS Backside mounting not available for SL versionPOWER SUPPLY (optional)UPS + 512kB MRAM Backside mounting not available for SL versionUPS + 512kB MRAM Backside mounting not available for SL versionKit for ATX mode power sup internal cable and connectorBATTERYIx CR2032 Internal MicroscBATTERYIx CR2032 Internal MicroscNo. S. CERTIFIEDInternal cable and connector	SSD/HDD alter-	SSD mSATA	1x onboard conne
INTERFACES USB 2.0 (Type-A) - 1x U SB 2x USB 2.0 (Type-A) - 1x U X INTERFACES SERIAL 1x RS232 (DB3 VIDEO 1x DVI-1 (Resolution up to 1920; included) 1x RS232/422/485 (DB15M) + 1 X RS232/422/485 (DB15			1x onboard connec
INTERFACES SERIAL 1x RS232 (DBS VIDEO 1x DVI-I (Resolution up to 1920) included) 1x DVI-I (Resolution up to 1920) included) ADD-ON INTERFACES (optional) not available for SL version Position A (max 1) 1x RS232/422/485 (DB15M) + 1 1x RS232/422/485 (DB15M) isolate 2x RS232 (DBS 2x USB 2.0 (Typ 1x Gigabit Etherne Bluetooth 4.3 and/or 1x Cellular module (World GPRS, UMTS/HSPA of Bluetooth 4.3 and/or 1x Cellular module (world GPRS, UMTS/HSPA of 0 riser card, ma EXPANSION SLOTS only S1 version 1x PCI half-length or 1x PCI on riser card, ma POWER SUPPLY INPUT UPS with external battery pa (backside or separate available for SL version UPS with external battery pa (backside or separate POWER SUPPLY (optional) UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal NCR2032 Internal COS. CERTIFIED 1x CR2032 Internal NCR2032 Internal COS CERTIFIED		LAN	
ADD-ON 1x DVI-I (Resolution up to 1920): included) INTERFACES (optional) not available for SL version Position A (max 1) NTERFACES (optional) not available for SL version Position B (max 1) SLOTS only S1 version POWER SUPPLY INPUT UPS with external battery part (backside or separate or available for SL version) POWER SUPPLY (optional) UPS + 512kB MRAM Backside mounting not available for SL version UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector or available for SL version UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector or available for SL version BATTERY 1x CR2032 Internal O.S. CERTIFIED N		USB	2x USB 2.0 (Type-A) • 1x U
ADD-ON INTERFACES (optional) not available for SL version Position A (max 1) 1x RS232/422/485 (DB15M)+1 1x RS232/422/485 (DB15M) isolate 2x RS232 (DB 2x USB 2.0 (Typ 2x USB 2.0 (Typ 2x USB 2.0 (Typ 2x USB 2.0 (Typ 1x Wi-Fi module (IEEE 802.11 a/b/ Bluetoth 4.2 and/or 1x Cellular module (world GPRS, UMTS/HSPA c EXPANSION SLOTS only S1 version 1x PCI half-length or 1x PCI on riser card, max POWER SUPPLY INPUT UPS Backside mounting not available for SL version UPS with external battery par (backside or separate available for SL version POWER SUPPLY (optional) UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal Microso Microso	INTERFACES	SERIAL	1x RS232 (DB
ADD-ON INTERFACES (optional) not available for SL version Ix RS232/422/485 (DB15M) isolate 2x RS232 (DB3 2x USB 2.0 (Typ 1x Gigabit Etherne Ix Wi-Fi module (IEEE 802.11 a/b/ Bluetooth 4.2 and/or 1x Cellular module (world GPRS, UMTS/HSPA c EXPANSION SLOTS only S1 version POWER SUPPLY INPUT Ix PCI half-length or 1x PCI on riser card, mathematication POWER SUPPLY UPS Backside mounting not available for SL version UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector MUPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector BATTERY Ix CR2032 Internal O.S. CERTIFIED M		VIDEO	
not available for SL version Position B (max 1) Ix Wi-Fi module (IEEE 802.11 a/b/ Bluetooth 4.2 and/or 1x Cellular module (world GPRS, UMTS/HSPA or gPOWER SUPPLY INPUT POWER SUPPLY INPUT Ix PCI half-length or 1x PCI on riser card, max power supply POWER SUPPLY (optional) UPS + 512kB MRAM Backside mounting not available for SL version UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector in the connector in th			1x RS232/422/485 (DB15M) isolate 2x RS232 (DB
SLOTS only ST version on riser card, ma POWER SUPPLY INPUT UPS Backside mounting not available for SL version UPS with external battery part (backside or separate) UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector) µUPS + 512kB MRAM Kit for ATX mode power sup internal cable and connector) BATTERY 1x CR2032 Internal O.S. CERTIFIED Mathematical	not available for		1x Wi-Fi module (IEEE 802.11 a/b/ Bluetooth 4.2 and/or 1x Cellular module (world
POWER SUPPLY (optional) UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector to available for SL version µUPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector to available for SL versions µUPS + 512kB MRAM Backside mounting not available for SL versions Kit for ATX mode power sup internal cable and connector to available for SL versions µUPS + 512kB MRAM ONS. CERTIFIED 1x CR2032 Internal Microso Microso		only S1 version	
POWER SUPPLY (optional) Backside mounting not available for SL version UPS with external battery pa (backside or separate backside mounting not available for SL version UPS + 512kB MRAM Backside mounting not available for SL version Kit for ATX mode power sup internal cable and connector µUPS + 512kB MRAM Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal 0.S. CERTIFIED N	POWER SUPPLY IN	PUT	
POWER SUPPLY (optional) Backside mounting not available for SL version Kit for A1X mode power sup internal cable and connector µUPS + 512kB MRAM ATX only S0/S1 versions Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal 0.S. CERTIFIED Microso Microso		Backside mounting not	
ATX only S0/S1 versions Kit for ATX mode power sup internal cable and connector BATTERY 1x CR2032 Internal O.S. CERTIFIED Microso Microso		Backside mounting not	
only S0/S1 versions internal cable and connector BATTERY 1x CR2032 Internal O.S. CERTIFIED Microson Microson Microson		µUPS + 512kB MRAM	
0.S. CERTIFIED			
Micro	BATTERY		1x CR2032 Internal
OPERATING TEMPERATURE 0°C -	0.S. CERTIFIED		
	OPERATING TEMPE	RATURE	0°C -
STORAGE TEMPERATURE	STORAGE TEMPER	ATURE	
OPERATING/STORAGE RELATIVE HUMIDITY	OPERATING/STOR	AGE RELATIVE HUMIDITY	
APPROVALS CE UL 508	APPROVALS		

1. Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control soft

)	BM2200							
IP20								
-								
ing	Book mounting							
bass steel	Aluminum alloy							
GHz (2.42GHz Burst) • 64b	it • 4 cores / 4 threads • 2MB L2 cache • 22nm							
el® Bay Trail • Included into	processor chip (SoC)							
cs for Intel Atom® process	sor Z3700 series • 688MHz/854MHz							
Programmable ti	Programmable time period							
Discrete TPM 2.0 mo	dule (optional)							
DDIMM DDR3L module)	2GB or 4GB or 8GB (1x SODIMM DDR3L module)							
ast SATA II slot onboard w	ith external access (up to 240GB)							
ector for direct insertion o	of SSD mSATA SATA II (up to 960GB)							
ectors for SSDs/HDDs 2,5"	SATA II with internal installation kit							
2x Gigabit Etherr	net (RJ45)							
JSB 3.0 (Type-A)	2x USB 2.0 (Type-A) • 1x USB 3.0 (Type-A) front							
89M)	-							
)) VGA adapter	1x DVI-I (Resolution up to 1920x1080 • VGA adap- ter included) or 1x RJ45 connector for RVL							
1x USB 2.0 (Type-A) ied + 1x USB 2.0 (Type-A) 39M) ipe-A)	1x RS232/422/485 (DB15M) isolated + 2x RS232 (DB9M) 1x RS232/422/485 (DB15M) isolated + 1x Gigabit Ethernet (RJ45)							
et (RJ45))/g/n/ac, 2.4GHz/5GHz • .2) ¹ dwide LTE Cat 4, GSM/ coverage) ¹	-							
Cle x1 half-length, nax 3W	-							
24VDC (18÷32VDC	C) isolated							
ack (Pb • 12V/2,5Ah) e mounting)	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)							
pply (push button, r for remote control)	-							
Supercapacitors µUPS	S + 512kB MRAM							
pply (push button, r for remote control)	-							
al access	1x CR2032 Removable front access							
Microsoft Windows 7 Pro/Ultimate 32/64bit oft Windows Embedded Standard 7E/7P 32/64 bit osoft Windows 10 IoT Enterprise 2016/2019 64bit								
0°C ÷ 50°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)								
-10°C ÷ 60	0°C							
20% ÷ 90% RH (non-condensing)								
	CE cULus Listed							
ware is installed on the sy	/stem.							

61

PB2250 & BM2250



FANLESS

X

- Intel Atom® x5 e x7 processor of SoC Apollo Lake generation
- RAM up to 8GB
- DIN rail mounting available (only BM2250)
- Available in SL version with reduced depth and SO version with the possibility to install additional interfaces (only PB2250)

TECHNICAL DATA

		PB2250	BM2250			
PROTECTION GRAD	E	IP2	0			
0405	Installation	Wall mounting	Book/DIN mounting			
CASE	Material	Zinc-coated skin pass steel	Aluminum alloy			
PROCESSOR (solde	red on-board)	Intel Atom® x5-E3930 1.30Ghz (1.80Ghz Burst) • 6 Intel Atom® x7-E3950 1.60Ghz (2.00Ghz Burst) • 6				
CHIPSET		Intel® Apollo Lake • Included	l into processor chip (SoC)			
VIDEO CONTROLLE	R	Intel® HD Graphics 500 integrated in x5 Intel® HD Graphics 505 integrated in x7	•			
ТРМ		Intel® PTT (TPM integrated) • Disc	crete TPM 2.0 module (optional)			
SYSTEM MEMORY	with x5-E3930	4GB LP-DDI	R4 module			
RAM	with x7-E3950	4GB or 8GB LP-	-DDR4 module			
MASS STORAGE	CFast	1x bootable CFast SATA III slot onboar	d with external access (up to 240GB)			
MASS STORAGE	M.2 SSD	1x onboard connector for direct insertior	n of M.2 2242 SATA III SSD (up to 480GB)			
	LAN	2x Gigabit Ethernet (RJ45)				
INTERFACES	USB	3x USB 3.0 (Type-A)				
	VIDEO	1x DisplayP	1x DisplayPort++ V1.2			
ADD-ON INTERFACES (optional)	Position A (max 1) only S0 version and BM	1x RS232/422/485 (DB15) 1x RS232/422/485 (DB15M) is 2x USB 2.0 1x Gigabit Ethernet (RJ4	olated + 1x USB 2.0 (Type-A) I (Type-A)			
POWER SUPPLY IN	PUT	24VDC (18÷32)	/DC) isolated			
POWER SUPPLY (optional)	ATX only S0 version and BM	Kit for ATX mode power supply (push button, internal cable and connector for remote control)	Kit for ATX mode power supply (connector for remote control)			
BATTERY		1x CR2032 Int	ernal access			
0.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019 64 bit				
OPERATING TEMPE	RATURE	0°C ÷ 50°C				
STORAGE TEMPER	ATURE	-5°C ÷ 60°C				
OPERATING/STORAGE RELATIVE HUMIDITY 20% ÷ 90% RH (non-condensing)			on-condensing)			
APPROVALS		CE cULus Listed				



- Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Available in RVL version (BM3300 RVL) for the remotation of the DVI-D and USB 2.0 signals up to 100m

DOWNLOAD THE PRODUCT SHEET





REMOTE VIDEO LINK



PROTECTION GRADE		IP20		
CASE	Installation	Book mounting		
	Material	Aluminum alloy		
PROCESSOR (soldered	on-board)	Intel® Celeron® 3955U 2.00GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-6100U 2.30GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6300U 2.40GHz (3.00GHz Turbo) 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i7-6600U 2.60GHz (3.40GHz Turbo) 64bit • 2 cores / 4 threads • 4MB Smart cache • 14nm		
CHIPSET		Intel® Skylake U PCH (Platform Controller Hub) • Included into processor chip (Soc)		
VIDEO CONTROLLER		Intel® HD Graphics 510 integrated in Intel® Celeron® processor • 300MHz/900MHz Intel® HD Graphics 520 integrated in Intel® Core™ i3 and i5 processors • 300MHz/1GHz Intel® HD Graphics 520 integrated in Intel® Core™ i7 processor • 300MHz/1,05GHz		
WATCHDOG		Programmable time period		
трм		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)		
SYSTEM MEMORY RAM		4GB or 8GB or 16GB (1x SODIMM DDR4 module)		
	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)		
MASS STORAGE	SSD mSATA	1x onboard connector for direct insertion of SSD mSATA SATA III		
	SSD/HDD	1x onboard connector for SSD/HDD 2.5" SATA III with internal installation kit		
	LAN	3x Gigabit Ethernet (RJ45)		
INTERFACES	USB	1x USB 3.0 (Type-A) front • 2x USB 3.0 (Type-A)		
	VIDEO	1x DVI-D (Resolution up to 1920x1200) or 1x RJ45 connector for RVL		
ADD-ON INTERFACES (optional)	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)		
POWER SUPPLY INPUT		24VDC (18÷32VDC) isolated		
POWER SUPPLY (optional)	UPS	UPS with external battery pack (Pb• 12V/2,5Ah) (separate mounting)		
BATTERY		1x CR2032 Removable front access		
0.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 32/64 bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit		
OPERATING TEMPERATURE		0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)		
STORAGE TEMPERATU	RE	-10°C ÷ 60°C		
OPERATING/STORAGE RELATIVE HUMIDITY		20% ÷ 90% RH (non-condensing)		
APPROVALS		CE cULus Listed		

PB3400/3600 & BM3400/3600



- Intel[®] Celeron[®], Core[™] i3, i5, i7 processors of Skylake and Kaby Lake generation
- RAM up to 32GB
- Built-in UPS with external battery pack (optional)
- Built-in supersapacitors µUPS, with 512kB MRAM for retentive data management (optional)
- PB3400/3600 available in S0, S1 and D2 version, with possibility to install additional interfaces, PCI/PCIe expansion slots and extractable drives slots for 2,5" SSDs/HDDs
- BM3400/3600 available in S0 and S2 versions, with the possibility to install additional interfaces and PCI/PCIe expansion slots, both with predisposition for extractable drawer kit for SSD/HDD: D0 (no kit), D1 (one kit) and D2 (two kits)
- Available with additional RVL (Remote Video Link) interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

GALLERY



PB3400/3600 - (S0 Version)



PB3400/3600 - (D2 Version)



BM3400/3600 - (S0 Version)

COMPARISON TABLE

		BM 3400/3600				
		SO		S2		
	DO	D1	D2	DO	D1	D2
ADD-ON INTERFACES (optional)	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
EXPANSION SLOTS PCI/PCIe	×	×	×	2	2	2
INTERNAL INSTALLATION KIT for SSDs/HDDs 2,5" SATA III	1	1	1	1, 2	1, 2	1, 2
EXTRACTABLE DRAWER KIT for SSDs/HDDs 2.5" SATA III	×	1	2	×	1	2



PB3400/3600 - (S1 Version)

PB3400/3600 & BM3400/3600

TECHNICAL DATA

		PB3400/3600	BM3400/3600		
PROTECTION GRADE		IP20			
CASE	Installation	Wall mounting	Book mounting		
	Material	Zinc-coated skin pass steel	Aluminum alloy		
PROCESSOR (soldered	xx3400	Intel® Core™ i3-6100E 2.70GHz 64bit • 2 c Intel® Core™ i5-6440EQ 2.70GHz (3.40GHz Turbo) 6	cores / 2 threads • 2MB Smart cache • 14nm ores / 4 threads • 3MB Smart cache • 14nm 34bit • 4 cores / 4 threads • 6MB Smart cache • 14nm 34bit • 4 cores / 8 threads • 8MB Smart cache • 14nm		
on-board)	xx3600	Intel® Core™ i5-7440EQ 2.90GHz (3.60GHz Turb	2 cores / 4 threads • 3MB Smart cache bo) 64bit • 4 cores / 4 threads • 6MB Smart cache bo) 64bit • 4 cores / 8 threads • 8MB Smart cache		
	xx3400	Intel® HM170 PCH (Platform Controlle	r Hub) with integrated RAID controller		
CHIPSET	xx3600	Intel® HM175 PCH (Platform Controlle	r Hub) with integrated RAID controller		
	S2 version with 2x PCIe x4	-	Intel® CM236 PCH (Platform Controller Hub) with integrated RAID controller		
VIDEO CONTROLLER	xx3400	Intel [®] HD Graphics 530 integrated in Inte	el® Celeron™ processor • 350MHz/950MHz el® Core™ i3 processor • 350MHz/950MHz º Core™ i5 and i7 processors • 350MHz/1GHz		
UNITABLER	xx3600	Intel® HD Graphics 630 integrated in Intel® Core™ i3 processor • 350MHz/950MHz Intel® HD Graphics 630 integrated in Intel® Core™ i5 and i7 processors • 350MHz/1GHz			
WATCHDOG		Programmab	le time period		
ТРМ		Intel® PTT (TPM integrated) • Dis	screte TPM 2.0 module (optional)		
SYSTEM MEMORY RAM		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)			
	Cfast	1x bootable CFast SATA III slot onboa	ard with external access (up to 240GB)		
	SSD mSATA	1x onboard connector for direct insertion of SSD mSATA SATA III (up to 960 GB)			
MASS STORAGE	SSD/HDD	1x onboard connector for SSD/HDD 2,5" SATA III with internal installation kit	1x or 2x onboard connectors for SSDs/HDDs 2,5″ SATA III with internal installation kit (2x not available for S0 version)		
EXTRACTABLE	only D1 version	-	1x extractable SSD/HDD 2,5" SATA III unit		
MASS STORAGE	only D2 version	2x extractable SSDs/I	HDDs 2.5" SATA III units		
RAID		Rai	d 0, 1		
	LAN	4x Gigabit Et	thernet (RJ45)		
	USB	3x USB 3.0 (Type-A) • 2x USB 2.0 (Type-A)	2x USB 3.0 (Type-A) • 2x USB 2.0 (Type-A) • 1x USB 3.0 (Type-A) front		
	SERIAL	1x RS23	2 (DB9M)		
	VIDEO	1x DVI-D (Resolutio	on up to 1920x1080)		
	Position A (max 1)	1x RS232/422/485 (DB15M) i 2x RS23	5M) + 1x USB 2.0 (Type-A) isolated + 1x USB 2.0 (Type-A) i2 (DB9M) .0 (Type-A)		
ADD-ON INTERFACES (optional)	Position B (max 1)	1x or 2x RJ45 connectors for RVL 1x Gigabit Ethernet (RJ45) 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) ¹ and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage) ¹	1x or 2x RJ45 connectors for RVL (2x not available for S0 D2 version) 2x DisplayPort++ V1.2		
EXPANSION	only S1 version	1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W	-		
SLOTS	only S2 version	-	1x PCIe x4 half-length + 1 x PCI half-length or 2x PCIe x4 half-length, on riser card, max 10W total		
			2VDC)isolated		

TECHNICAL DATA

		PB3400/3600	BM3400/3600			
	UPS	UPS with external battery pack (Pb • 12V/2.5Ah) (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2.5Ah) (separate mounting)			
POWER SUPPLY (optional)	UPS + 512kB MRAM	-	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (separate mounting)			
	µUPS + 512kB MRAM	Supercapacitors µ	UPS + 512kB MRAM			
	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)	-			
BATTERY		1x CR2032 Internal access	1x CR2032 Removable front access			
0.S. CERTIFIED	xx3400	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 32/64 bit Microsoft Windows Embedded Standard 7E/7P 32/64 bit				
	xx3600	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit				
OPERATING	without forced ventilation	0°C ÷ 50°C 0°C ÷ 45°C (24x7 HDD or Core i7 processor) 5°C ÷ 45°C (Standard HDD)				
TEMPERATURE	with forced ventilation (only S2 version)	-	0°C ÷ 50°C 0°C ÷ 50°C (24x7 HDD or Core i7 processor) 5°C ÷ 45°C (Standard HDD)			
STORAGE TEMPER	ATURE	-10°C ÷ 60°C				
OPERATING/STOR	AGE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)			
FORCED VENTILATION (optional)		- Forced ventilation (2x tachometric fans 4 mm), required to ensure: - operating temperature 0°C ÷ 50°C (24x Core i7 processor) - use of expansion cards, max 2009				
APPROVALS		CE cULus Listed				

1. Wi-Fi and Cellular modules cannot be used if CODESYS SoftPLC control software is installed on the system.

PB3500 & BM3500



- Intel® Celeron®, Core™ i3, i5, i7 processor of Kaby Lake generation
- RAM up to 16GB
- Built-in UPS with external battery pack (optional)
- Built-in supercapacitors $\mu \text{UPS},$ with 512kB MRAM for retentive data management (optional)
- Available in SL version with reduced depth, S0 version with the possibility to install additional interfaces and S1 version with one PCI or PCIe expansion slot
- Available in RVL version (BM3500 RVL) or with additional RVL (Remote Video Link) interface (PB3500) for the remotation of the DVI-D and USB 2.0 signals up to 100m

GALLERY



PB3500 - (SL Version)



PB3500 - (S1 Version)

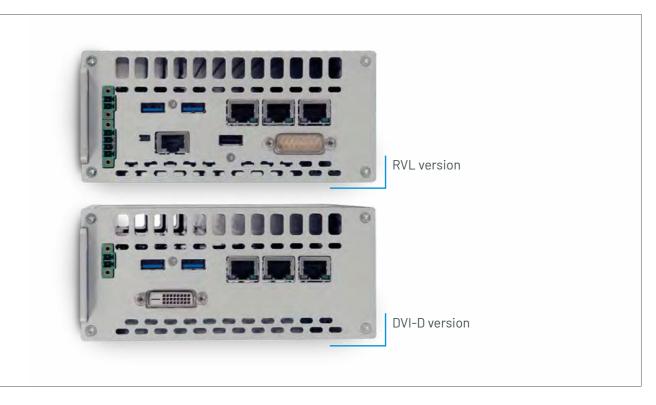
VERSIONS

CODESYS OPTIONAL

RVL

FANLESS

X



PB3500 - (S0 Version)



PB3500 & BM3500

TECHNICAL DATA

		PB3500	BM3500			
PROTECTION GRAD	E	IP	20			
0105	Installation	Wall mounting	Book mounting			
CASE	Material	Zinc coated stainless steel	Aluminum alloy			
PROCESSOR (solde	red on-board)	Intel® Celeron® 3965U 2.20GHz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-7100U 2.40GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7300U 2.60GHz (3.50GHz Turbo) 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i7-7600U 2.80GHz (3.90GHz Turbo) 64bit • 2 cores / 4 threads • 4MB Smart cache • 14nm				
CHIPSET		Intel® Kaby Lake U PCH (Platform Controlle	r Hub)• Included into processor chip (SoC)			
VIDEO CONTROLLE	R	Intel® HD Graphics 610 integrated in Intel Intel® HD Graphics 620 integrated in Int Intel® HD Graphics 620 integrated in Inte Intel® HD Graphics 620 integrated in Inte	tel® Core™ i5 processor • 300MHz/1GHz I® Core™ i5 processor • 300MHz/1.10GHz			
WATCHDOG		Programmabl	e time period			
ТРМ	Discrete version only for S0/S1 versions and BM	Intel® PTT (TPM integrated) • Dis	crete TPM 2.0 module (optional)			
SYSTEM MEMORY R	AM	4GB or 8GB or 16GB (1x	SODIMM DDR4 module)			
	Cfast	1x bootable CFast SATA III slot onboa	rd with external access (up to 240GB)			
MASS STORAGE	SSD mSATA	-	1x onboard connector for direct insertion of SSD mSATA SATA III			
	SSD M.2	1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x2 SSD (up to 512GB) or M.2 2280 NVMe PCIe x4 SSD (up to 1TB) ¹ or M.2 2242 SATA III SSD (up to 480GB)	-			
	SSD/HDD only S0/S1 versions and BM	1x onboard connector for SSD/HDD 2.	5" SATA III with internal installation kit			
	LAN	3x Gigabit Eth	nernet (RJ45)			
	USB	4x USB 3.0 (Type-A)	1x USB 3.0 (Type-A) front • 2x USB 3.0 (Type-A) top			
INTERFACES	SERIAL	1x RS232 (DB9M)	-			
	VIDEO	1x DisplayPort++ V1.2	1x DVI-D (Resolution up to 1920x1200) or 1x RJ45 connector for RVL			
ADD-ON	Position A (max 1)	1x RS232/422/485 (DB15 1x RS232/422/485 (DB15M) is 2x RS232 2x USB 2.0	solated + 1x USB 2.0 (Type-A) 2 (DB9M)			
INTERFACES (optional) not available for SL version	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x DVI-D (Resolution up to 1900x1200) 1x RJ45 connector for RVL 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/ 5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/ GPRS, UMTS/HSPA coverage)	-			
EXPANSION SLOTS	only S1 version	1x PCI half-length or 1x PCIe x4 half-length, on riser card, max 5W	-			
POWER SUPPLY INI	PUT	24VDC (18÷32	VDC) isolated			
	UPS	UPS with external battery pack (Pb • 12V/2.5A) (backside or separate mounting)	UPS with external battery pack (Pb • 12V/2,5Ah) (separate mounting)			
POWER SUPPLY (optional)	UPS + 512kB MRAM	-	UPS with external battery pack (Pb • 12V/2,5Ah) + 512kB MRAM (separate mounting)			
	µUPS + 512kB MRAM	-	Supercapacitors µUPS + 512kB MRAM			
	ATX only S0/S1 versions	Kit for ATX mode power supply (push button, internal cable and connector for remote control)	-			

TECHNICAL DATA

	PB3500	BM3500					
BATTERY	1x CR2032 internal access	1x CR2032 removable front access					
0.S. CERTIFIED	Microsoft Windows 10 IoT Enterprise 2019/2016 64 bit						
OPERATING TEMPERATURE	0°C ÷ 0°C ÷ 45°C (24x7 HDD or I 5°C ÷ 45°C (S	ntel® Core™ i7 processor)					
STORAGE TEMPERATURE	-10°C	÷ 60°C					
OPERATING/STORAGE RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)						
APPROVALS	C cULus	-					

 The M.2 NVMe PCIe x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCIe x2). Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCIe x2 SSDs).

PB5400/5600



• Intel® Celeron®, Core™ i3, i5, i7 processors of Skylake and Kaby Lake generation

- RAM up to 32GB
- · Available in S0 version with the possibility to install additional interfaces, S1 version with one PCIe expansion slot and S3 version with three PCIe expansion slots
- Available with additional RVL interface for remotation of the DVI-D and USB 2.0 signals up to 100m (optional)
- Available with 115/230VAC power supply (optional)

GALLERY



PB5400/5600 - (S0 Version) - 24VDC



PB5400/5600 - (S1 Version) - 24VDC



PB5400-5600 - (S3 Version) - 24VDC

DETAIL - EXTRACTABLE DRIVES SLOT



PB5400/5600 - (S0 Version) - 230VAC



PB5400/5600 - (S1 Version) - 230VAC



PB5400-5600 - (S3 Version) - 230VAC

PB5400/5600

TECHNICAL DATA

		PB5400/5600					
PROTECTION GRADE	E	IP20					
0405	Installation	Wall mounting					
CASE	Material	Zinc-coated skin pass steel					
PROCESSOR	PB5400	Intel® Core™ i3-6100 3.70GHz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-6500 3.20GHz (3.60GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-6700 3.40GHz (4.00GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm					
(soldered on-board)	PB5600	Intel® Celeron® G3930E 2.90Ghz 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-7101E 3.90Ghz 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7500 3.40Ghz (3.80GHz Turbo) 64bit • 4 cores / 4 threads • 6MB Smart cache • 14nm Intel® Core™ i7-7700 3.60Ghz (4.20GHz Turbo) 64bit • 4 cores / 8 threads • 8MB Smart cache • 14nm					
CHIPSET		Intel® C236 PCH (Platform Controller Hub) with integrated RAID controller					
	PB5400	Intel® HD Graphics 530 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.05GHz Intel® HD Graphics 530 integrated in Intel® Core® i7 processor • 350MHz/1.15GHz					
VIDEO CONTROLLER	PB5600	Intel® HD Graphics 610 integrated in Intel® Celeron® processor • 350MHz/1GHz Intel® HD Graphics 630 integrated in Intel® Core® i3 and i5 processors • 350MHz/1.10GHz Intel® HD Graphics 630 integrated in Intel® Core® i7 processor • 350MHz/1.15GHz					
WATCHDOG		Programmable time period					
ТРМ		Intel® PTT (TPM integrated) • Discrete TPM 2.0 module (optional)					
SYSTEM MEMORY RAM (soldered)		4GB (1x 4GB SODIMM DDR4 module) 8GB (2x 4GB SODIMM DDR4 module) 16GB (2x 8GB SODIMM DDR4 module) 32GB (2x 16GB SODIMM DDR4 module)					
_	Cfast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)					
MASS STORAGE _	SSD M.2	1x onboard connector for direct insertion of M.2 2280 NVMe PCIe x4 SSD (up to 512GB) or M.2 2242 SATA III SSD (up to 480GB)					
	SSD/HDD	2x onboard connectors for SSDs/HDDs 2.5" SATA III with internal installation kit					
EXTRACTABLE	S0/S1/S3 versions	1x extractable SSD/HDD 2.5" SATA III unit					
MASS STORAGE	only S1/S3 versions	2x extractable SSDs/HDDs 2.5" SATA III units					
RAID		Raid 0, 1					
-	LAN	4x Gigabit Ethernet (RJ45)					
INTERFACES	USB	4x USB 3.0 (Type-A)					
INTERFACES	SERIAL	1x RS232 (DB9M)					
	VIDEO	1x DVI-D (Resolution up to 1920x1080)					
ADD-ON	Position A (max 1)	1x RS232/422/485 (DB15M) + 1x USB 2.0 (Type-A) 1x RS232/422/485 (DB15M) isolated + 1x USB 2.0 (Type-A) 2x RS232 (DB9M) 2x USB 2.0 (Type-A)					
INTERFACES (optional)	Position B (max 1)	1x Gigabit Ethernet (RJ45) 1x or 2x RJ45 connectors for RVL 2x DisplayPort++ V1.2 1x Wi-Fi module (IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2) and/or 1x Cellular module (worldwide LTE Cat 4, GSM/GPRS, UMTS/HSPA coverage)					
	only S1 version	1x PCIe x16 half-length, on riser card, max 50W					
EXPANSION SLOTS	only S3 version	1x PCIe x16 half-length + 1xPCIe x4 half-length + 1xPCIe x1 half-length or 2x PCIe x8 half-length + 1x PCIe x4 half-length, on riser card, max 50W total					
POWER SUPPLY		24VDC (18÷32VDC) isolated					
INPUT	optional	115V/230VAC (85÷264VAC) isolated, autoranging					
POWER SUPPLY (optional)	ATX	Kit for ATX mode power supply (push button, internal cable and connector for remote control)					
BATTERY		1x CR2032 Internal access					

TECHNICAL DATA

0.S. CERTIFIED	PB5400	Micros Micros Microsoft
	PB5600	Micros Microsoft
OPERATING TEMPERATURE		0°C -
STORAGE TEMPERATURE		
OPERATING/STORAGE REL		
APPROVALS		

1

PB5400/5600

rosoft Windows 10 IoT Enterprise 2019/2016 64 bit Microsoft Windows 7 Pro/Ultimate 64 bit rosoft Windows Embedded Standard 7E/7P 64 bit ft Windows Server Embedded Standard 2019 R2 64 bit

osoft Windows 10 IoT Enterprise 2019/2016 64 bit it Windows Server Embedded Standard 2019 R2 64 bit

0°C ÷ 50°C C ÷ 45°C (24x7 HDD or Intel® Core™ i7 processor) 5°C ÷ 45°C (Standard HDD)

-10°C ÷ 60°C

20% ÷ 90% RH (non-condensing)

CE cULus Listed

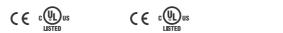
COMPARISON TABLE

									R Mar	
		PB2150 & BM2150	PB2200 & BM2200	PB2250 & BM2250	BM3300	PB3400 & BM3400	PB3500 & BM3500	PB3600 & BM3600	PB5400	PB5600
FANLESS		\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark	X	×
INSTALLATION		PB - Wall mounting BM - Book/DIN moun- ting	PB - Wall mounting BM - Book mounting	PB - Wall mounting BM - Book/DIN moun- ting	Book mounting	PB - Wall mounting BM - Book mounting	PB - Wall mounting BM - Book mounting	PB - Wall mounting BM - Book mounting	Wall mounting	Wall mounting
PROCESSORS	Model	Intel® Celeron® J1900	Intel® Celeron® J1900	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel® Celeron® 3955U Intel® Core™ i3-6100U Intel® Core™ i5-6300U Intel® Core™ i7-6600U	Intel® Celeron® G3900E Intel® Core™ i3-6100E Intel® Core™ i5-6440EQ Intel® Core™ i7-6820EQ	Intel® Celeron® 3965U Intel® Core™ i3-7100U Intel® Core™ i5-7300U Intel® Core™ i7-7600U	Intel® Core™ i3-7100E Intel® Core™ i5-7440EQ Intel® Core™ i7-7820EQ	Intel® Core™ i3-6100 Intel® Core™ i5-6500 Intel® Core™ i7-6700	Intel® Celeron® G3930E Intel® Core™ i3-7101E Intel® Core™ i3-7101E Intel® Core™ i7-7700
	Generation	Intel® Bay Trail	Intel® Bay Trail	Intel® Apollo Lake	Intel® Skylake	Intel® Skylake	Intel® Kaby Lake U	Intel® Kaby Lake	Intel® Skylake	Intel® Kaby Lake
SYSTEM MEMOR	RΥ	Up to 8GB	Up to 8GB	Up to 8GB	Up to 16GB	Up to 32GB	Up to 16GB	Up to 32GB	Up to 32GB	Up to 32GB
	LAN	2x RJ45	2x RJ45	2x RJ45	3x RJ45	4x RJ45	3x RJ45	4x RJ45	4x RJ45	4x RJ45
_	USB	1x USB 3.0 • 1x USB 2.0	2x USB 2.0 • 1x USB 3.0	3x USB 3.0	1x USB 3.0 • 2x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	3x USB 3.0 • 2x USB 2.0	4x USB 3.0	4x USB 3.0
INTERFACES	Serial	-	1x RS232 (DB9M)(PB only)	-	-	1x RS232 (DB9M)	1x RS232 (DB9M)(PB only)	1x RS232 (DB9M)	1x RS232 (DB9M)	1x RS232 (DB9M)
	Video	1x DVI-D	1x DVI-I	1x DisplayPort++ V1.2	1x DVI-D	1x DVI-D	1x DisplayPort++ V1.2	1x DVI-D	1x DVI-D	1x DVI-D
EXPANSION SLO	OTS PCI/PCIe	-	Up to 1 (PB only)	-	-	PB - Up to 1 BM - Up to 2	Up to 1 (PB only)	PB - Up to 1 BM - Up to 2	Up to 3	Up to 3
INTERNAL SSD/	/HDD	-	Up to 1	-	Up to 1	PB - Up to 1 BM - Up to 2	Up to 1	PB - Up to 1 BM - Up to 2	Up to 2	Up to 2
EXTRACTABLE	SSD/HDD	-	-	-	-	Up to 2	-	Up to 2	Up to 3	Up to 3
POWER SUPPLY	(INPUT	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC 115V/230VAC	24VDC 115V/230VAC
OPERATING SYS	STEMS	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 7 Microsoft Windows Embedded Standard 7 Microsoft Windows Server Embedded Standard Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC Microsoft Windows Server Embedded Standard
PAC VERSION *		X	\checkmark	X	X	\checkmark	×	\checkmark	X	X
CERTIFICATIONS	S									

 * with UPS + 512kB MRAM for retentive data management and Codesys software



C E CUL















CE CULUS

ULTRA-COMPACT IPCS

HIGH CAPACITIES OF PROCESSING

85%

60%

COMPACTNESS ERGONOMIC DESIGN

BM1XY FAMILY



- Ultra-compact design and anodized aluminum chassis
- Intel[®] Atom[™] x5, x7 processors of SoC Apollo Lake generation
- RAM up to 8GB
- Available with 4 ports Gigabit Ethernet switch (only BM121 and BM131)
- Available with Wi-Fi/Bluetooth interfaces and 4G Global modem (only BM122, BM130 and BM131)
- DIN rail mounting available
- Wall mounting available (only BM100)
- Built-in UPS with external battery pack (optional)

VERSIONS





BM100

BM110





BM121

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BM122



BM131



BM120



BM1XY FAMILY

TECHNICAL DATA

		BM100	BM110	BM120	BM121	BM122	BM130	BM131		
PROTECTION GRADE	IP rating		IP20							
	Installation	Book / DIN rail / Wall Mounting		ail Mounting						
CASE	Material			Anodized	aluminum allo	оу				
	Dimensions (w/o mounting)	100x100x39,4mm	100x100x58,4mm	10	10x100x79mn	ı	100×100	x100mm		
PROCESSOR (soldered	on-board)		Intel Atom® x5-E3930 1.3GHz (1.8 GHz Burst) • 2 cores / 2 threads • 2MB L2 cache • 14nm Intel Atom® x7-E3950 1.6GHz (2.0 GHz Burst) • 4 cores / 4 threads • 2MB L2 cache • 14nm							
CHIPSET			Intel® Apollo	Lake • Inclu	ded into proc	essor chip (SoC)			
VIDEO CONTROLLER) Graphics 500 integ) Graphics 505 integ							
TPM				Intel® PTT (TPM integrat	ed)				
SYSTEM MEMORY	with x5-E3930	2GB or 4GB SO- DIMM LP-DDR4 module		4G	B SODIMM LF	2-DDR4 mod	ule			
RAM (soldered)	with x7-E3950	4GB or 8GB SO- DIMM LP-DDR4 module		4GB or	8GB SODIMN	1 LP-DDR4 r	nodule			
MASS STORAGE	SSD M.2	1x on	board connector for	direct insert	ion of M.2 22	42 SATA III S	SSD (up to 480GE	3)		
	LAN	2x Gigabit Etl	hernet (RJ45)	4x Gigabit Ethernet (RJ45)	2x Gigabit (RJ4		4x Gigabit Ethernet (RJ45)	2x Gigabit Ethernet (RJ45)		
	LAN Switch			1x Unma- naged Gigabit Switch (4x RJ45)		-	1x Unmana- ged Gigabit Switch (4x RJ45)			
INTERFACES	USB	2x USB 3.0	О(Туре-А)	4x USB 3.0 (Type-A)		2x USB 3.0 (Type-A)	3.0 4x USB 3.0			
	SERIAL	-	-	1x RS232/ 422/485 (DB9M)	-		1x RS232/ 422/485 (DB9M)	-		
	VIDEO			1x Displa	yPort++ V1.2	V1.2				
	DIGITAL INPUT	-		2x Digi	al Input (0÷24V isolation 500V)					
	DIGITAL OUTPUT	-		2x Digita	l Output (N.O. max 200mA 24VDC)					
	Model		-			Bointe	c DPE109A (mPC	le interface)		
	Standard		-			IEEE 802.11 a/b/g/n/ac, 2.4GHz/5GHz • Bluetooth 4.2				
	Security		-			WEP 64/1	28bit, WPA, WPA	2, WPS, 802,1		
	RF Output Power		-			2.4G 5GF	Hz (802.11b): 18 d Hz (802.11n): 14 d Hz (802.11a): 13 d z (802.11ac): 10 d	IBm ± 2dB 3m ± 2dB		
Wi-Fi Module	RF sensitivity		-		11a, 20MHz:- MCS=0 PER @ -90 dBm, typical 11n, 20MHz:- MCS=0 PER @ -90 dBm, typical 11b, 20MHz@8%PER:- 11Mbps PER @ -91 dBm, typical <0,1% BER at -70dBm (Bluetooth)					
	Feature		-			Client	mode / Access	point mode		
	Antenna		_			2x R	P-SMA Female o	onnector		

TECHNICAL DATA

		BM100	BM110	BM120	BM121	BM122	BM130	BM131	
	Model	- SIMCom SIM7600G-H (mPCle interface)							
Cellulare Module	Frequency Bands		-			FDD-LTE: B1/B2/B3/B4/B5/B7/B8/B12/ B13/B18/B19/B20/B25/B26/B28/B66 TDD-LTE: B38/B39/B40/B41 UMTS/HSDPA/HSPA+: B1/B2/B4/B5/B6/ B8/B19 GSM/GPRS/EDGE: B2/B3/B5/B8			
	Data Transfer		-	up to 15	0Mbps(Downlac (Upload)	od)/50Mbps			
	SIM		-	1x Micro SIM card socket, push-push type					
	Antenna		-	2x SMA Female connector					
POWER SUPPLY INPUT	r	24VDC (18÷32VDC) isola					ed		
POWER SUPPLY (optional)	UPS	-		UPS with ext	ternal battery (separate r	y pack (NiMH • 12V/2,5Ah) mounting)			
BATTERY				1x CR2032	Internal acce	SS			
0.S. CERTIFIED			Microsoft	Windows 10 Io	T Enterprise	2016/2019 64	4 bit		
OPERATING	with x5-E3930	0°C ÷ 55°C			0°C÷				
TEMPERATURE	with x7-E3950			0°0	C÷50°C				
STORAGE TEMPERATU	E TEMPERATURE -10°C ÷ 60°C								
OPERATING/STORAGE	RELATIVE HUMIDITY	1TY 20% ÷ 90% RH (non-condensing)							
APPROVALS		CE cULus Listed							

COMPARISON TABLE

		BM100	BM110	BM120	BM121	BM122	BM130	BM131
INSTALLATION	l	Book/ DIN rail/ Wall mounting	Book/ DIN rail mounting	Book/ DIN rail mounting	Book/ DIN rail mounting	Book/ DIN rail mounting	Book/ DIN rail mounting	Book/ DIN rail mounting
PROCESSORS	Model	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom [®] x5-E3930 Intel Atom [®] x7-E3950	Intel Atom [®] x5-E3930 Intel Atom [®] x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950	Intel Atom® x5-E3930 Intel Atom® x7-E3950
	Generation	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake	Intel® Apollo Lake
SYSTEM MEMO	RY	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB	Up to 8GB
	LAN	2x RJ45	2x RJ45	4x RJ45	2x RJ45	2x RJ45	4x RJ45	2x RJ45
	LAN switch	-	-	-	1x Unmanaged Gigabit Switch (4x RJ45)	-	-	1x Unmanaged Gigabit Switch (4x RJ45)
	USB	2x USB 3.0	2x USB 3.0	4x USB 3.0	4x USB 3.0	2x USB 3.0	4x USB 3.0	4x USB 3.0
	Serial	-	-	1x RS232/422/485 (DB9M)	-	-	1x RS232/422/485 (DB9M)	-
INTERFACES	Video	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2	1x DisplayPort++ V1.2
	Digital input	-	2	2	2	2	2	2
	Digital output	-	2	2	2	2	2	2
	Wi-Fi module	X	X	X	X	\checkmark	\checkmark	\checkmark
	Cellular module	×	×	×	×	\checkmark	\checkmark	\checkmark
POWER SUPPL	Y INPUT	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC	24VDC
OPERATING SY	STEMS	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC	Microsoft Windows 10 IoT Enterprise LTSC			
CERTIFICATION	NS		C E CULUS	C E CULUS	C E CULUSTED	C E CULUS	C E CULUS	C E CUL



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38/100

ARM/VESA MOUNTING IPCS

HIGH PERFORMANCE WIDE CONFIGURABILITY AND EXPANDABILITY ELEGANT DESIGN EASE OF INSTALLATION

1

VK3500 SERIES



BUTTON AREA PAG. 118

ACCESSORI

PAG. 122

- VESA 75/100 or top/bottom arm mounting
- Available in landscape and portrait version
- Powder coated die-cast aluminum chassis with anti-scratch treatment
- 15.6", 18.5", 21.5" and 24" TFT LCDs in Wide aspect ratio for landscape version (VK3500 and VK3500-BA)
- 21,5" and 24" TFT LCDs in Wide aspect ratio for portrait version (VK3500P-BA)
- Front panels with minimized aluminum and glass True Flat (TFM) frame with multitouch projected capacitive touchscreen
- Full IP65 protection grade
- Available with configurable Button Area for the installation of Ø22 hard-wired elements (VK3500-BA and VK3500P-BA)
- Celeron®, Core™ processors of Kaby Lake generation
- Available with RVL technology for the remotation of the DVI-D and USB 2.0 signals up to 100m (optional)

TECHNICAL DATA

		VK3500-BA-TFM	VK3500-TFM	VK3500P-BA-TFM			
LED BACKLIGHT TFT L	.CD	15.6″ W - 15.6″ W - 18.5″ W - 18.5″ W - 21.5″ W - 24″W - 19	920x1080 1366x768 920x1080 920x1080	21.5″ W - 1920×1080 24″W - 1920×1080			
ORIENTATION		Lands	scape	Portrait			
TOUCHSCREEN			P-CAP M	lultitouch			
FRONT PANEL	Material		True Flat	Aluminum			
PROTECTION GRADE			Full	IP65			
	Installation	compatible		ension arm mounting system TARAPLUS/HASEKE ULT KUPPLUNG 48			
CASE	Material		Aluminum allo	by AN AB46400			
	Color		Anti-scratchable	painted - RAL 9006			
	Accesories		Side handles, perimetral	handle, keyboard holder kit			
BUTTON AREA (option	nal)	See dedicated section	-	See dedicated section			
PROCESSOR (soldered	d on-board)	Intel® Core™ i3 Intel® Core™ i5-7300U	Intel® Core™ 3965U 2.20GHz • 64bit • 2 cores / 2 threads • 2MB Smart cache • 14nm Intel® Core™ i3-7100U 2.40GHz • 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i5-7300U 2.60GHz (3.50GHz Turbo) • 64bit • 2 cores / 4 threads • 3MB Smart cache • 14nm Intel® Core™ i7-7600U 2.80GHz (3.90GHz Turbo) • 64bit • 2 cores / 4 threads • 4MB Smart cache • 14nm				
CHIPSET		Intel® Kaby Lake PCH-LP (Platform Controller Hub - Low Power) • Included into processor					
VIDEO CONTROLLER		Intel® HD Graphics 610 integrated in Celeron™ 3965U • 300MHz/900MHz Intel® HD Graphics 620 integrated in Core™ i3 processors • 300MHz/1.00GHz Intel® HD Graphics 620 integrated in Core™ i5 processors • 300MHz/1.10GHz Intel® HD Graphics 620 integrated in Core™ i7 processor • 300MHz/1.15GHz DirectX 12 and OpenGL 4.5 support					
WATCHDOG			Programmab	le time period			
TPM		Intel® PTT (TPM integrated)					
SYSTEM MEMORY RAM	1	4GB or 8GB or 16GB (1 x SODIMM DDR4 module)					
	CFast	1x bootable CFast SATA III slot onboard with external access (up to 240GB)					
MASS STORAGE	M.2 SSD	1x onboard con		of M.2 2280 NVMe PCIe x2 SSD (up to 512GB) CIe x4 SSD (up to 1TB) ¹			
	LAN		3x Gigabit Et	hernet (RJ45)			
INTERFACES	USB	3x USB 3	3.0 (Type-A) • 1x USB 3.0 (Typ	pe-A) rear access with protection cap			
	VIDEO (optional)	1x DisplayPort++ V1.2 or 1x RJ45 connector for RVL					
ADD-ON INTERFACES (optional)	Position A (max 1)		1 x RS232/422/48	2/485 (DB15M) 35 (DB15M) isolated :hernet (RJ45)			
CONNECTIVITY (option	nal)	1x Wi-F	Fi module (IEEE 802.11 a/b/g	ı/n/ac, 2.4GHz/5GHz • Bluetooth 5.1)			
POWER SUPPLY INPUT	Г		24VDC (18÷32	2VDC) isolated			
POWER SUPPLY (optio	onal) ATX	Kit for ATX mode power supply (internal cable and push button on button area)					
BATTERY		1x CR2032 Removable front access					
0.S. CERTIFIED		Microsoft Windows 10 IoT Enterprise 2016/2019 64bit					
OPERATING TEMPERA	TURE	0°C ÷ 50°C					
STORAGE TEMPERATU	JRE	-10°C ÷ 60°C					
OPERATING/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)					
APPROVALS		CE cULus Listed					

1. The M.2 NVMe PCIe x4 SSDs show actual performance that differs from the manufacturer's claims, as they are driven via 2 lanes (socket M.2 PCIe x2).Data transfer rates are about half of the declared value (comparable to M.2 NVMe PCIe x2 SSDs).

RACK MOUNTING IPCS

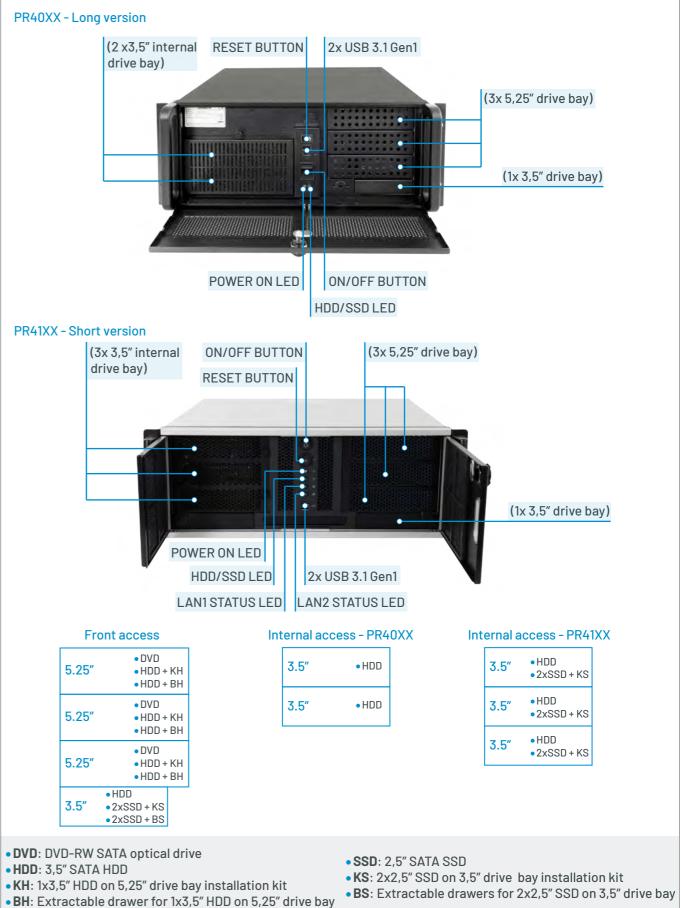
HIGH PERFORMANCE HIGH CONFIGURABILITY HIGH RELIABILITY MULTIPLICITY OF USE

PR4XXX SERIES



- Available in long (PR40XX) and short versions (PR41XX)
- 24/7 operation
- High processing capacity
- High reliability
- Multiplicity of use
- Intel[®] Core[™] i3, i5, i7 processors of Skylake, Kaby Lake and Coffee Lake generation

DETAIL - FRONT ACCESS



PR4XXX SERIES

TECHNICAL DATA

		PR4048	PR4148	PR4049	PR4149	PR4050	PR4150	PR4051	PR4151
					Cabinet rack	mount 19″ 4U			
-	ASEM Logo				Adhesi	ve label			
CASE -	Material	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel	Electro galvanized Steel	Hot dip galvanized Steel
CABINET FORMAT		Long	Short	Long	Short	Long	Short	Long	Short
MOTHERBOARD		Δ	TX format, D3	446-S2 (Fujits	1)		ATX format, D3	3646-S(Fujitsu	1)
PROCESSOR (soldered on-board) Intel® Core™ i3-6100 3.70GHz 64bit • 2 cores / 4 threads • 3MB Smart LGA1151 Intel® Core™ i5-6400 2.70GHz (3.30GHz Turbo) 64bit • 4 cores / 4 threads • 3MB Smart cache • 14nm · Socket LGA1151 Intel® Core™ i5-6400 · 3MB Smart cache • 14nm • 3MB Smart cache • 14nm · Socket LGA1151 Intel® Core™ i5-6400 · 3MB Smart cache • 14nm • 3MB Smart cache • 14nm · Socket LGA1151 Intel® Core™ i7-6700 · 6MB Smart cache • 14nm • 3MB Smart cache • 14nm · Socket LGA1151 Intel® Core™ i7-6700 · 6MB Smart cache • 14nm · 4MB Smart Cache • 14nm · Socket LGA1151 Intel® Core™ i7-6700 · 6MB Smart cache • 14nm · Socket LGA1151 Intel® Core™ i7-6700 · 4MB Smart Cache • · 8MB Smart Cache • · 8MB Smart Cache • · 8MB Smart Cache • · 14nm • Socket LGA1151 · Socket LGA1151 · 14nm • Socket LGA1151 · 300Hz (4.00GHz · 14nm • Socket LGA1151 · 300Hz (4.70GHz · 14nm • Socket LGA1151 · 300Hz (4.70GHz · 14nm • Socket LGA1151 · 14nm • Socket LGA1151 <th>bit• 4 cores • 6MB Smart m• Socket 1151 9™ 15-8400 00GHz Turbo) es / 6 threads cache • 14nm t LGA1151 e™ 17-8700 60GHz Turbo) res / 12 thre- mart cache • ket LGA1151 n™ E-2176G 70GHz Turbo) res / 12 thre- mart cache •</th> <th colspan="2">Smart Intel® Core™ i3-9100 3.60GHz (4.20GHz Turbo) 64bit • 4 cores / 4 threads 64Dit • 4 cores / 4 threads 64B Smart cache • 14nm • 6MB Smart cache • 14nm • Socket LGA1151 Intel® Core™ i5-9400 2.90GHz (4.10GHz Turbo) 64bit • 6 cores / 6 threads • 9MB Smart cache • 14nm • 9MB Smart cache • 14nm • Socket LGA1151 Intel® Core™ i7-9700 3.00GHz (4.70GHz Turbo) 64bit • 8 cores / 8 threads • 12MB Smart cache • • 12MB Smart cache • 14nm • Socket LGA1151</th>		bit• 4 cores • 6MB Smart m• Socket 1151 9™ 15-8400 00GHz Turbo) es / 6 threads cache • 14nm t LGA1151 e™ 17-8700 60GHz Turbo) res / 12 thre- mart cache • ket LGA1151 n™ E-2176G 70GHz Turbo) res / 12 thre- mart cache •	Smart Intel® Core™ i3-9100 3.60GHz (4.20GHz Turbo) 64bit • 4 cores / 4 threads 64Dit • 4 cores / 4 threads 64B Smart cache • 14nm • 6MB Smart cache • 14nm • Socket LGA1151 Intel® Core™ i5-9400 2.90GHz (4.10GHz Turbo) 64bit • 6 cores / 6 threads • 9MB Smart cache • 14nm • 9MB Smart cache • 14nm • Socket LGA1151 Intel® Core™ i7-9700 3.00GHz (4.70GHz Turbo) 64bit • 8 cores / 8 threads • 12MB Smart cache • • 12MB Smart cache • 14nm • Socket LGA1151						
CHIPSET		Intel® C236 Express Chipset with integrated RAID controller			Intel® C24	Intel® C246 Express Chipset with integrated RAID controller			
VIDEO CONTROLLER		integrated I i3 processor 050 Intel® HD 530 integr 0 ore™ i5 p 350MHz. Intel® HD G integrated I i7 processor 150 Multi Displa	raphics 530 ntel® Core™ • 350MHz/1. Graphics ated Intel® rocessor • /950MHz raphics 530 ntel® Core™ • 350MHz/1. GHz y supported to 3)	integrated I i5 processor 100 Intel® HD G integrated I i7 processor 150 Multi Displa	Intel® HD Graphics 630 integrated Intel® Core™ i5 processor • 350MHz/1. 10GHz Intel® HD Graphics 630 integrated Intel® Core™ i7 processor • 350MHz/1. 15GHz Multi Display supported (up to 3)		Graphics 630 Intel® Core™ r • 350MHz/1. GHz Graphics 630 Intel® Core™ r • 350MHz/1. GHz GHz r • 350MHz/1. GHz • 350MHz/1. GHz • 350MHz/1. GHz y supported to 3)	integrated i3 processor 100 Intel® UHD 0 integrated i5 processor 050 Intel® UHD 0 integrated i3 processor 200 Multi Displa	Graphics 630 ntel [®] Core [™] • 350MHz/1. GHz Graphics 630 ntel [®] Core [™] • 350MHz/1. GHz GHz • 350MHz/1. GHz y supported to 3)
GRAPHICS LIBRARY		Dir	extX 12 • Open	GL 4.4 suppor	ed	Dir	extX 12 • Open	IGL 4.5 suppor	ted
AUDIO				Realtek® ALC6	715.1-channel	High Definitio	n Audio CODE	С	
ETHERNET CONTROLLE	R		Intel® I210AT	and Intel® I219L	.M with suppo	rt of Intel® AM	T 11, WoL and N	1agic Packet™	
ТРМ					Discrete TPI	12.0 module			
SYSTEM MEMORY RAM				8GE 16GI 32GE	(2x 4GB SODI 3 (2x 8GB SOD 3 (2x 16GB SOD	MM DDR4 module) IMM DDR4 module) IMM DDR4 module) JIMM DDR4 module) JIMM DDR4 module)			
MASS STORAGE	M.2 SSD	1v ophoor	deannactorfa	- or direct inserti	on of SSD	1x onboard c		direct insertior SD (up to 1TB)	n of M.2 2280
TIADO OTUKAUL	SSD mSATA			II (up to 960GB				-	
	SSD/HDD			6x SATA 60	b/s ports for S	SSD 2,5"/HDD 3	3,5" SATA III		
RAID					Raid O,	1, 5, 10 ¹			

TECHNICAL DATA

		PR4048	PR4148	PR4049	PR4149	PR4050	PR4150	PR4051	PR4151
	External			1		(h=1,65″) H=1,00″)		1	
DRIVE BAY	Internal	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")	2x 3,5" (H=1,00")	3x 3,5" (H=1,00")
	LAN	2x Gigabit Ethernet (RJ45)							
	USB	2x U	SB 3.1 Gen1(Ty 2x USB 2.0 inte	/pe-A) front ac ernal connecto	a) • 4x USB 2.0 (Type-A)2x USB 3.1 Gen2 (Type-A) • 2x USB 3.1 Gen1 (Type-A)be-A) front access4x USB 2.0 (Type-A)rnal connector2x USB 3.1 Gen1 (Type-A) front accesType-A) internal2x USB 3.1 Gen2 Stick (Type-A) internal			ccess	
INTERFACES	SERIAL		1x RS232	2 (DB9M)			1x RS231 3x RS232 inter	2 (DB9M) rnal connector	-
	PERIPHERAL DEVICES		1:	x PS/2 Keyboa	rd port (purple	e)•1x PS/2 mot	use port (greer	n)	
	VIDEO				1x DVI-D • 2x D	isplayPort V1.2	2		
	AUDIO			1x Li	ne In • 1x Line	Out • 1x Microp	hone		
INTERFACES w/ SLOT	BRACKET		1x RS232 (I	DB9M) rear					
EXPANSION SLOTS		2x PCI full size (32 bit, 33MHz, Rev 2.3) 1x PCIe x16 (16 Lanes, Gen3) • 1x PCIe x16 (4 Lanes, Gen3) 1x PCIe x8 (1 Lane, Gen3) 1x PCIe x4 (4 Lanes, Gen3) • 1x PCIe x4 (1 Lane, Gen3)			6(4 Lanes,	2x PCI full size (32 bit, 33MHz, Rev 2.3) 1x PCIe x16 (16 Lanes, Gen3) • 1x PCIe x16 (4 Lanes, Gen3) 2x PCIe x8 (1 Lane, Gen3) 1x PCIe x1 (Gen3)			
POWER SUPPLY		Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging	Inpute voltage 110/230VAC • 400W or 650W, au- toranging Inpute voltage 110/230VAC • 2x 500W, auto- ranging, redundant	Inpute voltage 110/230VAC • 400W or 650W, au- toranging
0.S. CERTIFIED		Microsoft Windows 10 Microsoft Windows 2019/2016 64 bit Microsoft Windows 7 Pro/ Ultimate 32/64 bit Microsoft Windows 7 Pro/ Ultimate 32/64 bit Microsoft Windows 10 IoT Enterprise 2019/201 Microsoft Windows Em- bedded Standard 7E/7P Microsoft Windows 10 IoT Enterprise 2019/201				1			
SPECIAL FEATURES		24/7 operation							
OPERATING TEMPERA	TURE	0°- 40°C with 24x7 HDD 5°- 40°C with standard HDD							
STORAGE TEMPERATI	JRE	-10°C ÷ 60°							
OPERATING/STORAGE RELATIVE HUMIDITY	E			2	20 ÷ 90% RH (n	on-condensing	g)		
APPROVALS					0	E			

For RAID 0, 1 configurations at least 2x HDDs 3,5" or 2x SSDs 2,5" are required For RAID 5 configuration a minimum of 3x HDDs 3,5" (no SSDs) are required For RAID 10 configuration, 4x HDDs 3,5" (no SSDs) are required.

INDUSTRIAL MONITORS

INTEGRATED RVL TECHNOLOGY

0051702	

DATA ANALYSIS	

0887-7-7.00

ROBUSTNESS **GREAT RELIABILITY**

MQ200 & MH200



- TFT LCDs in 12.1" and 15" in 4:3 aspect ratio, 17" and 19" in 5:4 aspect ratio, 12.1", 15.6", 18.5",
- 21.5" and 24" in Wide aspect ratio
- Resolution up to Full HD
- Aluminum (ALU) e aluminum True Flat (TF) front panels with resistive touchscreen
- Aluminum and glass True Flat front panels with multitouch projected capacitive touchscreen (TFM)
- Stainless steel True Flat (TFK) front panels with resistive touchscreen
- MQ family with the new minimized frame
- Front IP65 protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- ATEX certification for QT-TFM version (optional)
- Available in RVL version (MQR200 & MHR200) for the remotation of the DVI-D and USB 2.0 signals up to 100m
- Available with 110/230VAC power supply

TECHNICAL DATA

		MQ200-ALU	MQ200-TFM	MQ200-TFK	MH200-ALU	MH200-TF
LED BACKLIGHT TFT LCI)	12.1" W - 1280x800 15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24" W - 1920x1080			12.1″ - 800×600 12.1″ - 1024×768 15″ - 1024×768 17″ - 1280×1024 19″ - 1280×1024	
CUT-OUT			QΤ		ŀ	łT
TOUCHSCREEN		Resistive 5 wires	P-CAP Multitouch		Resistive 5 wires	
FRONT PANEL		Aluminum	True Flat Aluminum	True Flat Stainless Steel	Aluminum	True Flat Aluminum
FRONT USB			-		1x USB 2.0 (Typ	pe-A), protected
_	IP rating	IP65 -	frontal	IP69K - frontal	IP65 -	frontal
PROTECTION GRADE	NEMA rating			UL Type 1, 4x (in- door only) and 12	UL Type 1, 4x (indoor only) and 12	
0405	Installation	Panel mounting				
CASE Material		Zinc-coated skin pass steel				
VIDEO INPUT	MQ/MH	1x DisplayPort 1x DVI-D				
	MQR/MHR	1x RJ45 connector for remotation of DVI-D1				
USB INPUT -	MQ/MH	1x USB 2.0 HUB input (Type-B)				
USB INFO I	MQR/MHR		1x RJ45 con	nector for remotation	of USB 2.0 ¹	
USB OUTPUT		3x USB 2.0 (Type-A)				
	Optional	1x USB 2.0 (Type-A) rear				
POWER SUPPLY INPUT		24VDC(18÷32VDC)isolated				
		110V/230VAC (90÷264VAC) isolated, autoranging				
OPERATING TEMPERATU	IRE	0° ÷ +50°C				
STORAGE TEMPERATUR	E	-5° ÷ +60°C				
OPERATION/STORAGE R	ELATIVE HUMIDITY	Y 20% ÷ 90% RH (non-condensing)				
APPROVALS		CE CE CE CULus Listed CE CULus Listed CULus Listed CULus Listed				

1. The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals



REMOTE VIDEO LINK

MK200 SERIES FillSimi ho 000 0 00 00 **DOWNLOAD THE PRODUCT SHEET** CUL US REMOTE • VESA 75/100 or top/bottom arm mounting VIDEO LINK

BUTTON AREA

ACCESSORI

PAG. 122

PAG. 118

- Available in landscape and portrait version
- Powder coated die-cast aluminum chassis with anti-scratch treatment
- 15.6", 18.5", 21.5" and 24" TFT LCDs in Wide aspect ratio for landscape version (MK200-TFM and MK200-BA-TFM)
- 21,5" and 24" TFT LCDs in Wide aspect ratio for portrait version (MK200P-BA-TFM)
- Resolution up to Full HD
- New front panels with minimized aluminum and glass True Flat frame with multitouch projected capacitive touchscreen
- Full IP65 protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- Available with configurable Button Area for the installation of Ø22 hard-wired elements (MK200-BA-TFM and MK200P-BA-TFM)
- Available in RVL version (MKR version) for the remotation of the DVI-D and USB 2.0 signals up to 100m

TECHNICAL DATA

		MK200-TFM	MK200-BA-TFM	MK200P-BA-TFM	
LED BACKLIGHT TFT LCD		15.6" W - 1366x768 15.6" W - 1920x1080 18.5" W - 1366x768 18.5" W - 1920x1080 21.5" W - 1920x1080 24" W - 1920x1080		21.5″ W - 1920×1080 24″ W - 1920×1080	
ORIENTATION		Land	scape	Portrait	
TOUCHSCREEN			P-CAP multito	buch	
FRONT PANEL			True Flat Alum	inum	
PROTECTION GRAI	DE		Full IP65		
	Installation	VESA 75/100 or pole/suspe	nsion arm mounting system co HASEKE ULT KUPF	mpatible with RITTAL CP40/ROLEC TARAPLUS/ PLUNG 48	
CASE	Material	Aluminum alloy AN AB46400			
	Colour	Anti-scratchable painted - RAL 9006			
	Accessories	Side handles, perimetral handle, keyboard holder kit			
BUTTON AREA (optional)		- See dedicated section			
VIDEO INPUT		1x DisplayPort 1x DVI-D			
	Remote version MKR	1x RJ45 connector for remotation of DVI-D ¹			
USB INPUT		1x USB 2.0 HUB input (Type-B)			
USB INPUT	Remote version MKR	1x RJ45 connector for remotation of USB 2.01			
USB OUTPUT			3x USB 2.0 (Ty	pe-A)	
038 001201	Rear access	1x USB 2.0 (Type-A) with protection cap			
POWER SUPPLY IN	PUT	24VDC (18÷32VDC) isolated			
OPERATING TEMP	ERATURE	0° ÷ +50°C			
STORAGE TEMPER	ATURE	-5° ÷ +60°C			
OPERATION/STOR	AGE RELATIVE HUMIDITY	TY 20% ÷ 90% RH (non-condensing)			
APPROVALS		CE cULus Listed			

The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals 1.



- Monitors specifically developed for Food&Beverage and chemical/pharma applications
- Stainless steel (AISI 304L) chassis with sloping surfaces to avoid dust accumulation

STAINLESS

IP69K

STEEL

(100)

BUTTON AREA

PAG. 120

- Stainless steel (AISI 304L) hygienic screws with under-head gasket
- Fully cleanable blue silicone gaskets
- 18.5″ TFT LCDs in Wide aspect ratio
- Resolution up to Full HD
- Stainless steel (AISI 304L) True Flat front panels with resistive touchscreen
- Top/bottom arm mounting
- Up to full IP69K protection grade
- Video input: 1x DVI-D and 1x DisplayPort
- Available with configurable Button Area for the installation of hard-wired elements: Ø22 cleanable silicon elements, or Ø30 low profile stainless steel elements
- Available in RVL version (MXR200) for the remotation of the DVI-D and USB 2.0 signals up to 100m

GALLERY



TECHNICAL DATA

		MX200	MX200-BA	
ED BACKLIGHT TFT L	CD	18.5″ W - 1366x768 18.5″ W - 1920x1080		
TOUCHSCREEN		Resistive	5 Wires	
FRONT PANEL		True Flat Sta	inless Steel	
ROTECTION GRADE		Full IP69K	Full IP65	
UTTON AREA		-	See dedicated section	
	la stallation	6x M5 screws + gasket + technical drawing		
ASE	Installation	o Top/bottom arm mounting with custom	-	
-	Material	Stainless Steel AISI 304L		
		1x DisplayPort 1x DVI-D		
DEO INPUT	Remote version MXR	1x RJ45 connector for remotation of DVI-D1		
		1x USB 2.0 HUB input (Type-B)		
B INPUT	Remote version MXR	1x RJ45 connector for remotation of USB 2.0 1		
		3x USB 2.0)(Type-A)	
B OUTPUT	Optional	2x USB 2.0 (Type-A) rear access with protection cap		
WER SUPPLY INPUT	•	24VDC (18÷32	VDC) isolated	
ERATING TEMPERAT	TURE	0° ÷ +50°C		
ORAGE TEMPERATU	RE	-5° ÷ +60°C		
ERATION/STORAGE	RELATIVE HUMIDITY	20% ÷ 90% RH (non-condensing)		
PPROVALS		CE cULus Listed		

The same RJ45 connector is used for remotation of DVI-D and USB 2.0 signals



COMPARISON TABLE

			d e seecc 4	
		MK200	MX200	MQ200 & MH200
	Wide sizes	15,6", 18,5", 21,5" and 24"	18,5"	12,1", 15,6", 18,5", 21,5" and 24"
FRONT	Narrow sizes	-	-	12,1", 15", 17", 19"
PANELS	Types	ALU	TFK	ALU, TF, TFM, TFK
_	Touchscreen technology	Multitouch	Resistive	Resistive Multitouch
PROTECTION G	RADE	Up to Full IP65	Up to Full IP69K	Up to Full IP69K
CASE MATERIA	L	Aluminum alloy AN AB46400	Stainless Steel AISI 304L	Zinc-coated skin pass steel
INSTALLATION	I	VESA 75/100 or pole/suspension arm mounting	Top/bottom arm mounting with custo- mized flange	Panel mounting
ACCESSORIES (optional)		Side handles Perimetral handle Keyboard holder kit	-	-
BUTTON AREA (optional)		\checkmark	\checkmark	×
POWER SUPPL	Y INPUT	24VDC	24VDC	24VDC 110V/230VAC
CERTIFICATION	٧S			

* only for QT-TFM





INTEGRATED UPS

CONVERTER ASEM has developed an integrated UPS (Uninterruptable Power Supply) system for its IPCs to prevent sudden shutdowns with consequent data loss or damage due to unexpected primary power supply failures. The control electronics are integrated into the power supply module to ensure maximum reliability and noise immunity to maintain the IPC and UPS communication interfaces within the system.

The control logic, organised on several levels, is entirely designed and developed by the ASEM R&D Team and includes:

- a hardware section capable of switching the power source of the primary voltage to the battery and vice versa in just microseconds
- a configurable hardware section for monitoring battery status and managing the charging and discharging phases
- a microcontroller-based control section for managing system states and interfaces with the IPC
- a high-level, Windows-based, user-configurable software section for diagnosing the system and battery pack status and managing shutdowns

The architecture is common to all systems and is customised by configuring specific parameters according to the type of use and consumption to optimise battery life

SOFTWARE

The UPS system operation is managed by high-level software, developed for Windows, divided into two parts:

- a service for monitoring the supply voltage and battery status and managing potential shutdowns
- a graphic application for configuring the behaviour in the event of a primary power failure and checking diagnostics

Furthermore, a regular system shutdown is commanded irrespective of the set parameters if a voltage below the minimum is measured to protect the battery from abnormal decay and avoid unexpected shutdowns

CONFIGURABLE SWITCH-OFF INTERVAL FROM 10 SECONDS TO 10 MINUTES

INDICATION OF REMAINING AUTONOMY CALCULATED ON ACTUAL SYSTEM CONSUMPTION

REAL-TIME BATTERY STATUS DIAGNOSTICS

LOG FUNCTIONS WITH DATA HISTORICISATION

INTEGRATION WITH THE USER APPLICATION

BATTERY PACK TYPES

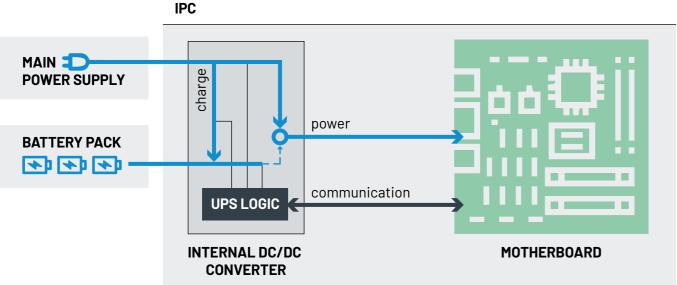
1) LEAD-ACID BATTERY

00000000

Lead-acid cell battery packs, compared to more modern technologies, are larger and bulker but they can supply high peak currents and operate over a wide temperature range (well above the 0-50°C guaranteed for systems). They consist of six elements for a nominal voltage of 12 V and can deliver a maximum of 100 W for approximately 2 minutes. They also integrate a temperature sensor and a protection circuit that cuts off the connection if the current is too high or the voltage is too low.

2) NICKEL-METAL-HYDRIDE (NIMH) BATTERIES

Battery packs with Ni-MH cells are characterised by a smaller size compared to lead-acid batteries and lower self-discharge during storage. They consist of 10 elements for a nominal voltage of 12V and can output a maximum of 60W for about 10 minutes. They also integrate a temperature sensor, a protection circuit that cuts off the connection if the current is too high or the voltage too low, and a switch for disconnecting the battery during transport.





INSTALLATION OF BATTERY PACKS

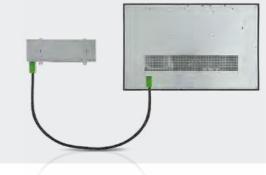
ASEM offers several installation options to choose the best location, facilitating wiring and/or replacement operations.



DIRECT ON THE SYSTEM



SEPARATED FROM THE SYSTEM, UP TO A DISTANCE OF 3M



MASS STORAGE DEVICES

ASEM provides a wide choice of mass storage devices for expanding the various IPCs according to customer requirements. All mass storage devices are tried and tested to guarantee correct operation in all working environments.



LIST OF MASS STORAGE DEVICES:

- CFAST: available in ET (Extended Temperature) version
- SSDs: available in SATA, NVMe PCIe and ET (Extended Temperature) versions
- HDDs: available in 2.5", 3.5" SATA III and 24x7 versions



SSD COMPARISON TABLE

	SSD 2,5" SATA III	SSD mSATA Sata III	SSD M.2 2242 Sata III	SSD M.2 2280 NVMe PCIe x4
BM1XY FAMILY	X	X	\checkmark	X
xx2150	X	\checkmark	X	X
xx2200	\checkmark	\checkmark	X	X
xx2250	X	X	\checkmark	X
BM3300 & BM3500	\checkmark	\checkmark	X	X
xx3400 & xx3600	\checkmark	\checkmark	X	X
QT-HT-PB 3500	\checkmark	X	\checkmark	\checkmark
xx5400 & xx5600	\checkmark	X	\checkmark	\checkmark
VK3500	X	X	X	\checkmark
PR4x48	\checkmark	\checkmark	X	X
PR4x49	\checkmark	\checkmark	X	X
PR4x50	\checkmark	×	X	\checkmark
PR4x51	\checkmark	×	×	\checkmark

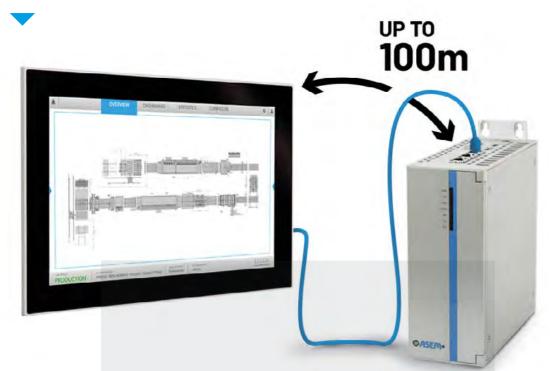
HDD COMPARISON TABLE

	HDD 2,5" SATA III	HDD 3,6" SATA III
BM1XY FAMILY	×	X
xx2150	×	X
xx2200	\checkmark	X
xx2250	×	×
BM3300 & BM3500	\checkmark	X
xx3400 & xx3600	\checkmark	×
QT-HT-PB3500	\checkmark	×
xx5400 & xx5600	\checkmark	X
VK3500	×	X
PR4x48	×	\checkmark
PR4x49	×	\checkmark
PR4x50	×	\checkmark
PR4x51	×	\checkmark





RVL (REMOTE VIDEO LINK)



VIDEO REMOTE CONTROL SOLUTIONS

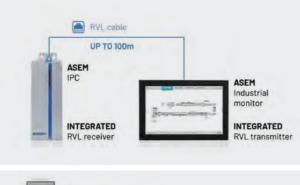
The ASEM Remote Video Link is an innovative technology for connecting industrial monitors up to 100 metres apart from the IPC using a single cable, through which DVI-D and USB 2.0 signals are sent using the HDBaseT standard.

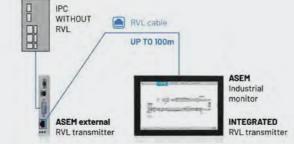
Signals are remoted up to 50 metres away using a Cat 5e SF/FTP cable or up to 100 metres away using a Cat 6A S/FTP cable.

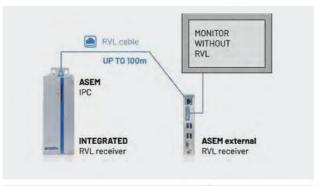
The use of an industrial standard Ethernet cable and the RJ45 connector allows easy cabling in tight spaces and in presence of mobile systems (e.g. Arm Mounting systems).

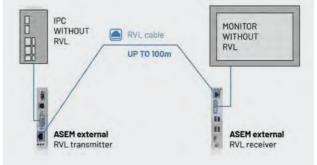
ASEM can also supply an external RVL transmitter and/or receiver to remote video signals using third-party IPCs or monitors.

Both are powered at 24VDC. The ASEM RVL technology can create connections at long distances between any industrial device and in any specific application. Here are the various cases of use:









1) IPC AND ASEM INDUSTRIAL MONITORS

ASEM integrates RVL technology in its IPCs and industrial monitors. No additional external systems are required to connect the proprietary systems.

2) ASEM INDUSTRIAL MONITORS

ASEM provides external RVL transmitters for easily connecting a third-party IPC (or ASEM IPC not equipped with an integrated RVL transmitter) to the integrated RVL technology of a proprietary monitor.

3) ASEM IPC

ASEM provides external RVL receivers for easily connecting a third-party industrial monitor to the integrated RVL technology of a proprietary IPC.

4) IPC AND INDUSTRIAL MONITORS NOT EQUIPPED WITH INTEGRATED RVL

ASEM provides external RVL receivers and transmitters for easily connecting an industrial monitor to IPCs not equipped with integrated RVL transmitters.



TPM TRUSTED PLATFORM MODULE

What is TPM? It is a technology designed to offer hardware and software security features. The Trusted Computing Group (TCG) is the organisation that publishes and maintains the TPM specifications according to the international standard 11889 ISO/ IEC.

The TPM is useful for generating, storing and restricting the use of cryptographic keys, passwords and certificates. The dTPM (Discrete Trusted Platform Module) is a dedicated microcontroller designed to protect the hardware. It integrates cryptographic keys into devices and is used for secure cryptographic processes and secure storage of critical data.

ASEM PRODUCTS TPM

	iTPM	dTPM
BM1XY FAMILY	\checkmark	×
QT/HT/PB/BM 2150	×	×
QT/HT/PB/BM 2200	×	\checkmark
QT/HT/PB/BM 2250	\checkmark	\checkmark
QT/HT/PB 3200	X	\checkmark
BM 3300	\checkmark	\checkmark
QT/HT/PB/BM 3400	\checkmark	\checkmark
QT/HT/PB/BM 3500	\checkmark	\checkmark
QT/HT/PB/BM 3600	\checkmark	×
QT/HT/PB/BM 5400	\checkmark	\checkmark
QT/HT/PB/BM 5600	\checkmark	\checkmark
HMI 100	\checkmark	X
VK 3500 SERIES	\checkmark	×

Integrated TPM has been recently introduced on x86-based machines. In this form, the TPM is integrated into a chipset component of the existing platform. For instance, the integrated x86-based TPM function is a security and management engine module and is logically isolated from the other engine modules.

- The TPM is an endpoint security technology (*)
- IEC 62443-4-2 cites TPM as the gold standard for meeting the requirements of SL3 and SL4
- It checks that the operating system and firmware of the device are not tampered with
- It stores digital credentials in a secure hardware-based repository
- It sets passwords and manages keys
- It expands the number of smart cards, fingerprint readers and remote controls for multi-factor authentication
- It encrypts files and folders to control access
- It establishes status information to enable endpoint integrity
- It enables more secure wireless, remote, and VPN access
- For Windows[®] 11, TPM 2.0 is a requirement (PC must have TPM enabled)

(*) Industrial Internet Security Framework (https:// www.iiconsortium.org/IISF.htm)

CONNECTIVITY •)

ASEM offers products with technologies that support the latest data communication interfaces and Internet connections.

Wi-Fi and Bluetooth, Cellular modules are available that can also be installed in combination with each other to provide multiple modes of use according to the specific needs of each automation environment, according to the requirements of Industry 4.0.

The technologies adopted offer intrinsic reliability, connection robustness and speed, which, using the recent 5G band present on the latest and future products, is combined with the guarantee of low latency and high capacity for data processing and simultaneous connections.

The MIMO and Diversity functions achieved through the dual antenna mounted directly on the product or remotely can be exploited to optimise connection stability and performance.

WIRELESS E BLUETOOTH CONNECTION TABLE

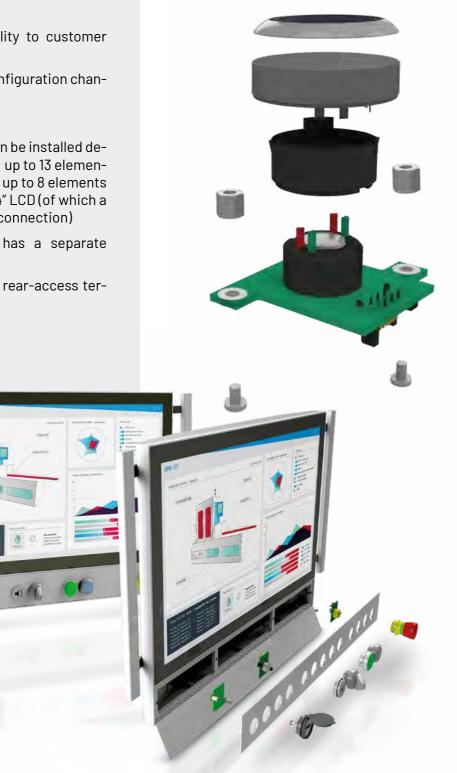
	Wi-Fi connection	Cellular connection
BM122	\checkmark	\checkmark
BM130	\checkmark	\checkmark
BM131	\checkmark	\checkmark
QT-HT-PB-BM 2150	\checkmark	\checkmark
QT-HT-PB 2200	\checkmark	\checkmark
QT-HT-PB 3400/3600	\checkmark	\checkmark
QT-HT-PB 3500	\checkmark	\checkmark
QT-HT-PB 5400/5600	\checkmark	\checkmark
VK3500	\checkmark	×



CONFIGURABLE CONTROL AREA

VK3500/MK200 SERIES

- Maximum configuration flexibility to customer specifications
- Frontally accessible for later configuration changes and/or additions
- Hard-wired connection modes
- The number of elements that can be installed depends on the size of the display: up to 13 elements on the landscape version and up to 8 elements on the portrait version with a 24" LCD (of which a maximum of 8 with hard-wired connection)
- The SIL3 emergency button has a separate hard-wired connection
- The elements are wired to two rear-access terminal blocks



Ø22 IP65 ELEMENTS



BUTTONS

- available in 5 colours (red, yellow, and black) green, blue, white)
 - translucent version in 5 colours (red, yellow, green, blue, white)
 - also with a customisable insert





SELECTORS

INDICATOR LIGHTS

- with key
- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)
- USB 2.0 (Type-A) • knob with incremental encoder
- buzzer







EMERGENCY STOP BUTTON SIL3

• opaque version in 2 colours (grey

• rotary or pull release, with or without LED indicator



ADDITIONAL INTERFACES • Gigabit Ethernet (RJ45) • Transponder RFID reader/writer LF (125 kHz) and HF (13,56 MHz)



ELEMENTS FOR MANAGING ATX MODE

- opaque version
- translucent version
- with key

FRONTALLY ACCESSIBLE FOR LATER CONFIGURATION CHANGES AND/OR ADDITIONS



CONFIGURABLE CONTROL AREA MX200

- Maximum configuration flexibility to customer specifications
- Frontally accessible for later configuration changes and/or additions
- Hard-wired connection modes
- Customer-selected elements can be Ø22 washable silicone or Ø30 low-profile stainless steel
- Up to 9 elements can be installed (of which a maximum of 8 with hard-wired connection)

Ø22 SILICONE ELEMENTS



INDICATOR LIGHTS

- available in 5 colours (red, yellow, translucent version in 5 colours green, blue, white)
 - grey opaque version

BUTTONS

EMERGENCY STOP BUTTON • rotary or pull release, with or without LED indicator

Ø30 STAINLESS STEEL, LOW-PROFILE ELEMENTS





• available in 5 colours (red, yellow, • translucent version in 5 colours • with key green, blue, white)

INDICATOR LIGHTS

• grey opaque version

BUTTONS

• with ring lighting



(red, yellow, green, blue, white)



SELECTORS

- with key
- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)



(red, yellow, green, blue, white)



SELECTORS

- light keyless
- 1(90°) or 2 (±40°, ±60°) positions (toggle or stable actuation)

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MECHANICAL ACCESSORIES

VK3500/MK200 SERIES

SIDE HANDLES





PERIMETER HANDLE





A set of two anodised aluminium side handles is available to facilitate system positioning

An anodised aluminium perimeter handle is available for easy positioning of the system and to protect the operator from accidental impacts

TYPES OF ASSEMBLY ARM/VESA Mounting IPC & Monitor

VK3500/MK200 SERIES

VESA MOUNTING

The VK3500 and MK200 systems are available with chassis having an attachment compatible with VESA 75/100 standards



ARM ASSEMBLY

VK3500 and MK200 systems are available with arm-mounted chassis compatible with RITTAL CP40/ROLEC TARAPLUS/ HASEKE ULT KUPPLUNG 48



KEYBOARD HOLDER KIT





An aluminium keyboard holder kit painted RAL 9006 is available for the permanent installation of a keyboard and/ or mouse of the customer's choice

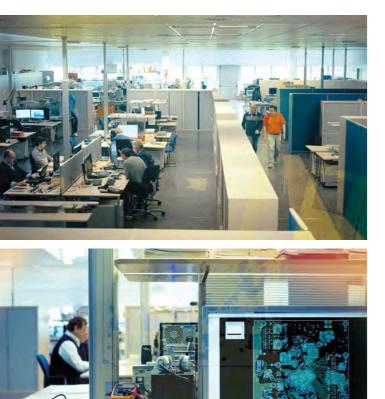
MX200 SERIES

The MX200 systems have a chassis with a specific attachment with six M5-type screws arranged with a 100mm centre distance. ASEM provides its customers with all the technical specifications for creating their own attachment flange. An arm-mounting flange for Ø48mm tubes is optionally supplied.





SERVICES AND SUPPORT



CUSTOMER-ORIENTED PHILOSOPHY

The ASEM customer-oriented philosophy means constant attention and care for the customer's needs and a comprehensive and qualified preand after-sales service. All company processes are designed and organised to ensure maximum customer satisfaction with excellent product quality and operational flexibility to respond promptly to changing market demands. ASEM ensures the quality of products and processes by systematically and rigorously applying its quality system according to UNI EN ISO 9001:2015. The quality system, introduced in 1999, is certified by Intertek and is constantly updated to improve the business operation effectiveness and efficiency.



ASSISTANCE AND REPAIRS

ASEM offers its customers excellent assistance and consulting services for hardware and software, in addition to a timely repair service for products and systems.

ASEM guarantees service through a team of specialised technicians to optimise service activities and minimise response times in the following ways:

PHONE HELP DESK SERVICE

- For hardware and systems, dial +39 0432 967250, from Mondays to Fridays from 9 a.m. to 12:30 noon and from 2 to 5:30 p.m.
- For software, dial +39 0362 859124, from Mondays to Fridays from 9 a.m. to 12:30 noon and from 2 to 5:30 p.m.

ONLINE HELP DESK SERVICE

Available for hardware and software, it allows access to the ASEM customer care directly online on the company website at:

www.asemautomation.com.

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With this quick and simple tool you can request service and technical support independently and RMA for any repair service and you can monitor the status of your request in real-time

E-MAIL SERVICE

Please send requests for hardware and software support to the following e-mail addresses:

- For hardware and systems: <u>suptec@asem.it;</u>
- For software: <u>supportsw@asem.it</u>

For software support, the "Asem Remote Support Tool" is also available at: <u>http://get.teamviewer.com/asemsup</u>





